

TEST AND MEASUREMENT PRODUCTS

Description

The E7804 is a quad channel, monolithic ATE pin electronics solution manufactured in a high-performance BiCMOS process.

The E7804 operates up to 133 MHz with up to 3V signals, and 100 MHz with 5V signals.

Each channel has a three-statable driver capable of generating 5.4V swings over a $-0.2V$, $+5.2V$ range. Drivers have independent high and low input levels that are buffered internally. Drivers feature a self-calibrating source impedance, programmable in the range 48Ω to 110Ω . The source impedance of all drivers matches $R_{REF}/100$, where R_{REF} is the external reference resistor. Each channel's dual comparator has a range of $-2.0V$ to $+5.5V$.

A channel's driver and comparators are connected internally via high voltage switches to the VIO pin. These switches provide a means to disconnect the driver and comparator from the VIO pin.

The E7804 contains an independent network of high voltage switches intended to connect an external Parametric Measurement Unit (EPMU) to any channel (or channels) output on the channel's POUT pin. The EPMU can have a range of $-4.75V$ to $+9.75V$, up to ± 40 mA. Typically, a channel's VIO and POUT pins are connected together externally.

Each channel contains a continuity test circuit (CTC) with a switch to connect it to the channel's POUT pin. This circuit forces a current up to $-250 \mu A$, and tests the resulting voltage with a 0 to $-2V$ programmable limit. The result is tested by the channel's comparator.

Each channel contains a $2K\Omega$ pull-up resistor with a switch to connect to the channel's POUT pin.

The channel's function and connections are programmed using a serial interface. An individual channel's function can be programmed, or a function of any set of channels (of multiple E7804s) can be programmed in parallel where each channel can belong to none, one, or more (up to 8) sets.

The E7804 features the inclusion of all four channels of pin electronics into a 128 pin package.

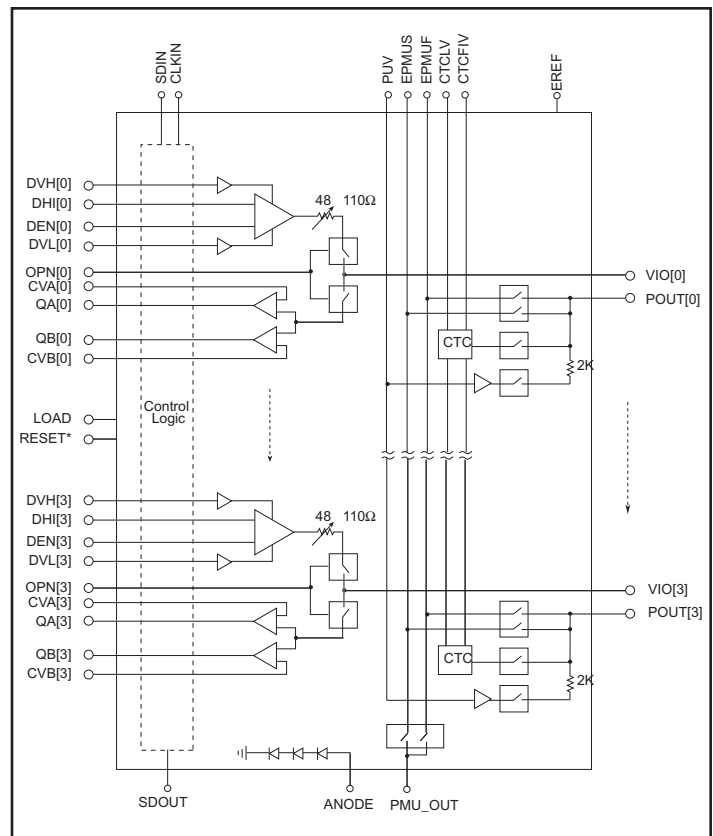
Features

- Four Integrated Three-Statable Drivers and Window Comparators
- Driver Voltage Range $-0.2V$, $+5.2V$
- Comparator Voltage Range $-2.0V$ to $+5.5V$
- Internal Disconnect Switches
- Internal Switches to an External PMU, Range $-4.75V$ to $+9.75V$, up to ± 40 mA
- Per Pin Pull-Up/Down $2K\Omega$ to (0V to $+5V$)
- Per Pin Continuity Test (Force Current up to $-250 \mu A$, Limit Voltage 0 to $-2V$)
- Self-Calibrating Driver Source Impedance to an External Reference (48Ω to 110Ω)
- Low Power Dissipation (250mW/channel quiescent)
- 128 Pin MQFP Package (with Internal Heat Spreader)

Applications

- Design for Test/Structural Pins in ATE
- Low Cost
 - Logic Testers
 - Memory Testers

Functional Block Diagram



TEST AND MEASUREMENT PRODUCTS
PIN Description

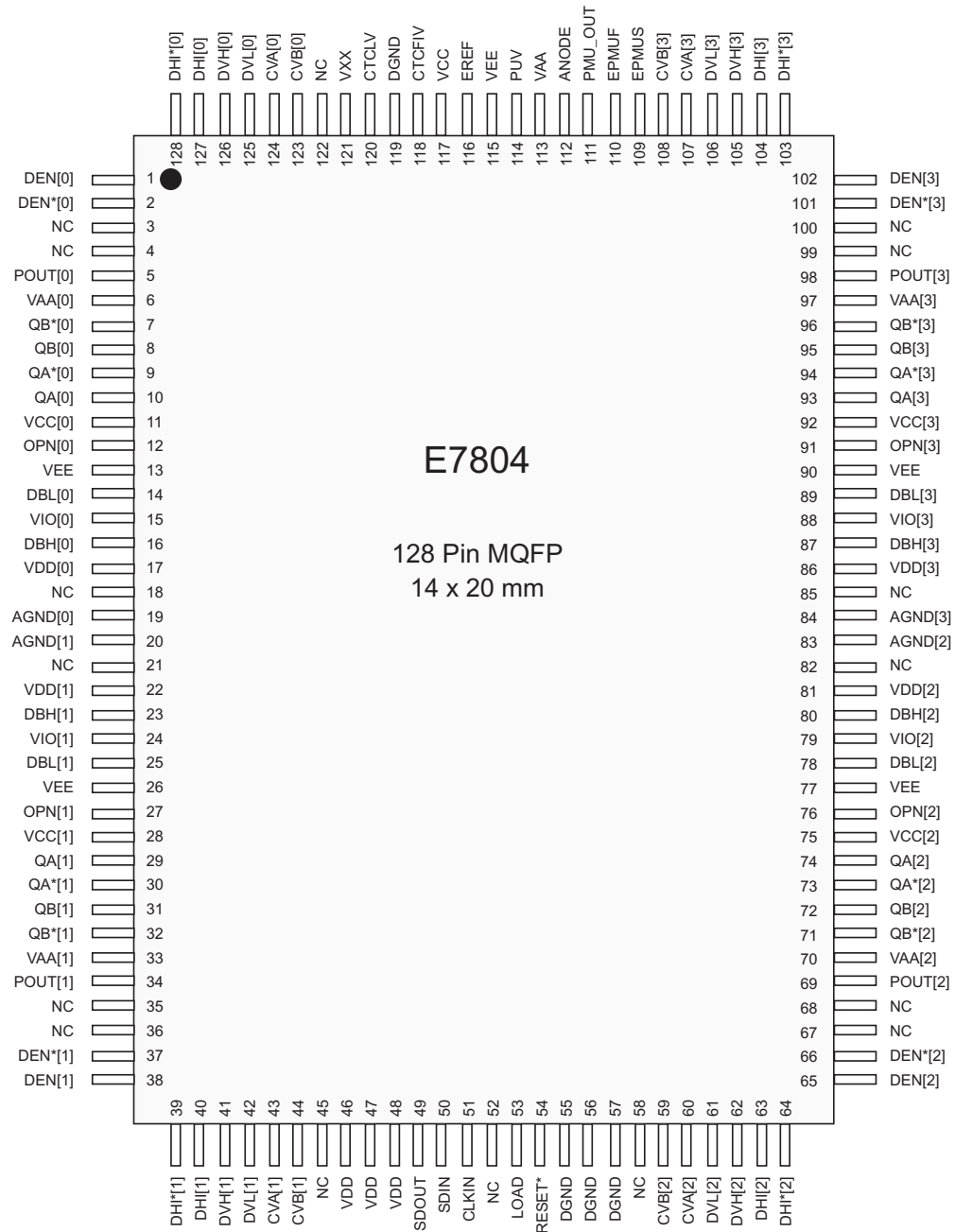
Pin #	Pin Name	Description
Driver, Comparator		
12, 27, 76, 91	OPN[0:3]	LV_TTL input that opens switches that disconnect the driver and comparator from VIO. This input overrides the individual switch register bits non destructively.
15, 24, 79, 88	VIO[0:3]	Device input/output of each channel.
127, 40, 63, 104 128, 39, 64, 103	DHI, DHI*[0:3]	"Flex" differential input digital pins which select the driver high or low level.
1, 38, 65, 102 2, 37, 66, 101	DEN, DEN*[0:3]	"Flex" differential input pins which control the driver being active or in a high impedance state.
126, 41, 62, 105 125, 42, 61, 106	DVH, DVL[0:3]	High impedance analog voltage inputs which determine the driver high and low levels. Connect a 0.22µf capacitor to ground for bypassing reasons.
16, 23, 80, 87 14, 25, 78, 89	DBH, DBL[0:3]	Driver level buffer outputs for high and low levels. Connect a 0.47 µF capacitor to ground for bypassing reasons.
124, 43, 60, 107 123, 44, 59, 108	CVA, CVB[0:3]	Analog inputs which set the A and B comparator thresholds.
10, 29, 74, 93 9, 30, 73, 94	QA, QA*[0:3]	Differential digital outputs of comparator A.
8, 31, 72, 95 7, 32, 71, 96	QB, QB*[0:3]	Differential digital outputs of comparator B.
PMU		
111	PMU_OUT	PMU test point for the anode of the thermal diode string.
5, 34, 69, 98	POUT[0:3]	Parametric Measure Unit input/output of each channel.
110	EPMUF	External parametric measurement for force input.
109	EPMUS	External parametric measurement for sense input.
114	PUV	Pull-up voltage input.
120	CTCLV	Continuity test circuit limit voltage.
118	CTCFIV	Continuity test circuit force current voltage.
Control		
54	RESET*	Active low chip reset. Resets the internal registers. It is an asynchronous input not requiring any CLKIN transitions.
51	CLKIN	Clock for the input data shift register.
50	SDIN	Serial data input.
49	SDOUT	Serial data out.
53	LOAD	Loads input data into central register.

TEST AND MEASUREMENT PRODUCTS
PIN Description (continued)

Pin #	Pin Name	Description
Power Supplies		
11, 28, 75, 92	VCC[0:3]	Analog positive power supply to channel high voltage circuitry (+8.25V).
117	VCC	Analog positive power supply to high voltage circuitry (+8.25V).
6, 33, 70, 97	VAA[0:3]	Analog positive power supply to channel circuitry (+5.0V nominal).
113	VAA	Analog positive power supply to core circuitry (+5.0V nominal).
13, 26, 77, 90, 115	VEE	Analog negative power supply (–5.0V nominal).
17, 22, 81, 86	VDD[0:3]	Digital positive power supply to channel comparator outputs (+3.3V nominal).
46, 47, 48	VDD	Digital positive power supply for core logic (+3.3V nominal).
19, 20, 83, 84	AGND[0:3]	Analog ground for channels.
55, 56, 57, 119	DGND	Digital ground for chip.
121	VXX	Switch positive power supply (VCC to VEE + 15V).
Miscellaneous		
116	EREF	External reference resistor input. REREF should be connected between EREF and AGND.
112	ANODE	Anode terminal of the on-chip thermal diode string. The pin is ESD protected to VXX, so when measuring the forward drop of the diode string, VXX should be either floating or $\geq 2V$. Cathode of diode string is connected to DGND.
3, 4, 18, 21, 35, 36, 45, 52, 58, 67, 68, 82, 85, 99, 100, 122	NC	No connect pin. No connection is made internally. These pins can be connected to a ground plane to assist in heat removal from the package.

TEST AND MEASUREMENT PRODUCTS

Pin Description (continued)



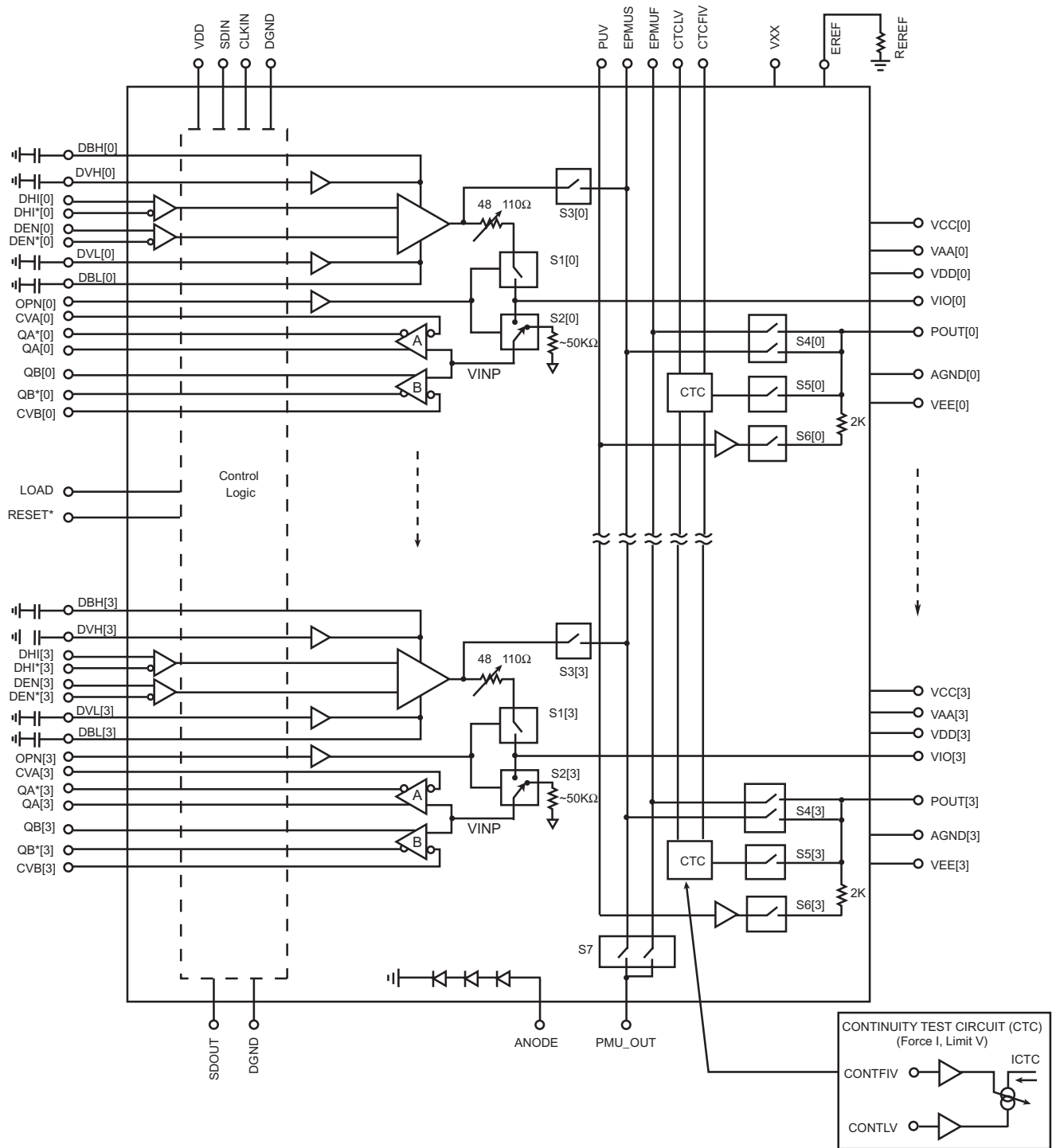


Figure 1. Detailed Block Diagram of E7804 Quad Driver and Window Comparator

TEST AND MEASUREMENT PRODUCTS

Circuit Description (continued)

Introduction

The four driver and window comparator channels of the E7804 are shown in Figure 1.

Driver

Refer to Table 1 showing the modes of operation of the driver.

Each channel's driver states of HiZ, force DVH voltage, force DVL voltage and Open can be controlled either by external input pins or via internal registers and bits programmed through the serial interface.

The HiZ/DVH/DVL states are controlled by the differential, external inputs, DHI/DHI* and DEN/DEN*. Each channel also has internal register bits (see Table 2, CH[0:3]_Relays_ & _States registers) SDHI and SDEN that accomplish the same functions as DHI and DEN. The serial register has another bit, SEN (Serial Enable) that allows the SDI and SDEN bits to override the external input pins DHI and DEN. If SEN is a logical "0", the SDHI and SDEN bits are ignored.

The DHI/DHI* and DEN/DEN* inputs are LV_TTL and differential LVDS, LV_PECL compatible.

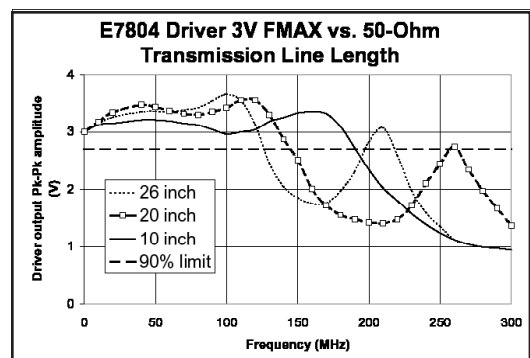
Unused DHI/DHI* or DEN/DEN* must be tied to valid logic levels.

Optimizing Driver Waveforms

The driver output pin, VIO, will normally be connected to the parametric output pin, POUT, when designed into a system. See the recommended 7804 Hookup drawing farther on in this datasheet. The POUT pin has a lumped capacitance associated with it that will degrade the signal integrity of the driver output waveform if not properly compensated for. The recommendation is to insert ferrite devices between the connection of POUT to VIO to accomplish this. For more details on how and why this approach is used, please read Semtech Application Note #ATE-A3 ATE-to-DUT Interface: Using Ferrites to Replace Relays for Lower Cost and Improved Performance.

The driver output impedance has a reactive component to it and will not completely absorb reflections from an

unterminated transmission line. This is common for all drivers, but more so in CMOS drivers than high speed bipolar stages. The figure here shows how transmission line length, here in the form of coaxial cable, will sum the reflections constructively and destructively to alter the peak-to-peak waveform excursions across frequency. More data on this performance and methods for optimizing signal integrity and extending Fmax will be available from Semtech staff. Check with Semtech for the latest information. From the graph below one can see that E7804 driver signals in excess of 150MHz are possible.



Driver Levels

Each channel's DVH and DVL are high input impedance voltage inputs which establish the channel driver's high and low levels. The driver's output range is -0.2V, +5.2V.

DVH to VIO and DVL to VIO offset errors are small, which allow the E7804 to be configured with common input levels to each channel (i.e. DVH[0:3] may be connected together externally, and the same for DVL[0:3]).

Driver Source Impedance

Drivers feature a self-calibrating source impedance calibrated to match an external resistor, RREF, connected between the EREF pin and analog ground. The source impedance can be chosen to calibrate in the range 48Ω to 110Ω using the calculation RREF/100.

A driver's source impedance is affected by its DVH and DVL levels, and therefore needs recalibrating whenever driver levels into the chip are changed. The calibration routine is initiated via the serial interface (see Table 2, calibrate_output_z register). When initiated, all channels are recalibrated in parallel.

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Circuit Description (continued)

Driver Connect/Disconnect

The driver output connects to the VIO output pin through an internal, normally open switch (S1). Refer to the Functional Block diagram in Figure 1 for Switch S1. This switch can be closed by serially programming the internal register bit for the appropriate channel (see Table 2, CH[0:3]_Relays_&_States registers) denoted as S1 to a logical "1". Logical "0" will open the switch. An external pin, OPN[0:3] one input for each channel, is combined with the register bit and will override the internal register bit and Open the S1 switch for the channel. In its low state, the OPN input will not override and force the switch closed however. (It should be noted that OPN=1 will also open S2 to disconnect the channel's window comparators from the VIO pin.) OPN is a fast way of disconnecting the lower voltage driver and comparator circuitry from the VIO pin. When the driver (and comparator) are disconnected, the voltage at VIO may be in the range of the VEE to VXX power supplies.

The high voltage disconnect switches permit an external Parametric Measurement Unit (PMU) to be connected to the VIO pin having a maximum range from VEE to VXX volts and up to ±40 mA.

This high voltage isolation also permits an external driver to apply up to VXX volts (when switches S1 and S2 are open) for high voltage applications.

Each driver may also be connected, internally, to EPMUS in order to measure its output for purposes of calibrating the DVH/L levels via switch S3.

Digital Inputs		OPN=0		OPN=1
		S1 Closed	S1 Open	X
DEN	DHI	VIO	VIO	VIO
1	0	DVL	Open	Open
1	1	DVH	Open	Open
0	0	HiZ	Open	Open
0	1	HiZ	Open	Open

OPN	(Open Channel Input)	Open	(Driver, Comp open/disconnected (see Table 3))
DVL	(Driver Low)	X	(Don't Care)
DVH	(Driver High)	S1	(Driver Output Switch)
HiZ	(High Impedance)		

Table 1. Driver Modes of Operation

Comparator

Each channel's two comparators, A and B, are combined to form a window comparator to determine whether its input, VINP, is above, below, or in between the two comparator thresholds (CVA and CVB). VINP is tied to the positive input of both comparators.

The CVA/B inputs should be driven from low impedance sources. There is an input non-linear current shift of ~15µA when the VINP signal to the comparator crosses polarity with respect to the CVA/B input. If the source impedance is too great, this could affect the accuracy of the compare points. The voltage source's output impedance should be below 4KΩ to avoid this. DAC or op amp outputs will have no issue with this. (If resistor dividers are used to create the CVA/B voltages, the voltage should be buffered to prevent this shift.)

VINP has a range of -2V, +5.5V, but is restricted to the range of the drivers whenever a comparator is connected to its driver (S1 and S2 switches both closed), namely -0.2V, +5.2V.

The comparator outputs are differential LVDS compatible on the QA/QA* and QB/QB* device pins. The output states of the comparators for each channel can also be read back using the serial interface. See Table 3, CH[0:3]_switches_&_states read back instruction for the individual channels.

Comparator Levels

Each channel's CVA and CVB are the window comparator's two threshold levels. CVA and CVB are high impedance voltage inputs that determine the thresholds at which the window comparator changes state. CVA and CVB have a range of -2.0V, +5.5V.

Comparator Connect/Disconnect

The window comparator input (VINP) connects to the VIO pin through an internal switch (S2). This switch can be closed to VIO by serially programming the internal register bit for the appropriate channel (see Table 2, CH[0:3]_switches_&_states registers) denoted as S2 to a logical "1". Logical "0" will open the switch from VIO. The comparator input is connected to approximately zero volts

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Circuit Description (continued)

when disconnected from VIO through ~50KΩ. To prevent the comparator outputs from switching due to noise when not in use, the CVA/B inputs should be parked >250mV from ground. An external pin, OPN[0:3] one input for each channel, is combined with the register bit, and will override the internal register bit and open the S2 switch for the channel. In its low state, the OPN input will not override and force the switch closed. (It should be noted that OPN=1 will also open S1 to disconnect the channel's driver output from the VIO pin.) OPN is a fast way of disconnecting the lower voltage driver and comparator circuitry from the VIO pin. When the comparator (and driver) are disconnected, the voltage at the VIO pin may be in the range of the VEE to VXX power supplies.

Parametric Measurements

The E7804 incorporates a switch matrix which permits an External Parametric Measurement Unit (EPMU) to be connected to one or more channel's POUT pin. The EPMU range is a function of the VEE and VXX power supplies with ±40 mA capability. Typically, POUT is connected directly to the VIO pin or connected by an inductor so as to minimize the effect of the capacitance at the POUT pin on the driver's waveform and maximum frequency.

The EPMUF and EPMUS inputs are force and sense inputs respectively and connect to the POUT output pin through an internal, normally open, dual switch (S4). There is one dual switch for each channel [0:3]. This switch can be closed by serially programming the internal register bit for the appropriate channel (see Table 2, CH[0:3]_switches_&_states registers) denoted as S4 to a logical "1". Logical "0" will open the switch. The switch and metal lines for the EMPUF path are sized to accommodate the higher currents (up to 40mA). Do not use EPMUS for higher currents. The EPMUS line is the Kelvin sense path for the external PMU.

Continuity Test Circuit

Each channel has a programmable Continuity Test Circuit (CTC) which can be switched to its POUT pin. The CTC sinks current in the range -15 to -250 μA as determined by the voltage of the CTCFIV input pin which is common to all CTC's.

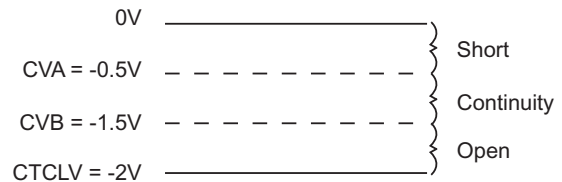
The relationship between the CTCFIV input voltage and the resulting current produced by the CTC uses the resistor Reref, as a reference. This gives a good degree of voltage to current accuracy. The relationship is:

$$ICTC = -1.09 * [CTCFIV(V) / Reref(\Omega)].$$

CTCLV input determines the voltage limit to which CTC may sink current. CTCLV has a range of 0 to -2.0V and is common to all channels' CTCs. With POUT, connected externally to VIO, then with CTC connected and sinking current, the resultant voltage at VIO can be tested by the channel's comparators. As this voltage could be as low as -2V, when performing a continuity test, a channel's driver should be disconnected in order to protect the driver, which has a range of -0.2V to +5.2V. The driver output should be disconnected by opening switch S1 when connecting the CTC to the POUT pin. The CTC connects to the POUT pin through the normally open switch S5. Switch S5 can be closed by serially programming a logical "1" via the internal register for the appropriate channel. See Table 2, "CH[0:3]_switches_&_states write instruction for the individual channels.

Note that the CTC's use the external resistor on the EREF pin to calculate the ICTC test currents. The driver output impedance calibration also uses this reference. If any CTC is switched in-circuit (S5 closed), then attempting to calibrate the driver output impedance will fail and not occur. No change to the calibration values will take place.

A typical continuity test will program the CTC's force current to -100 μA, its voltage limit at -2V, and CVA and CVB at -0.5V and -1.5V, respectively, so as to detect shorts, opens and continuity. typically, in this test, the DUT power supplies are all set to zero volts. The continuity test will determine if each pin of the DUT is connected to the pin channel in the tester without shorts to supplies or ground.



The tested pins will test good if the resulting voltage from a -100μA load on them results in ~-0.7V. This is the voltage

TEST AND MEASUREMENT PRODUCTS

Circuit Description (continued)

that will be present if the pin substrate or ESD diodes are present. A short can be detected if the resulting voltage is close to zero volts. An Open will be detected if the voltage goes close to -2V. The figure above illustrates this test with the CVA = -0.5V and CVB = -1.5V.

Pull-Up Resistor

Each channel has a 2KW (typ.) pull-up resistor that can be switched to its POUT. The effective pull-up, including resistor and switch, is in the range 1KW to 3KW.

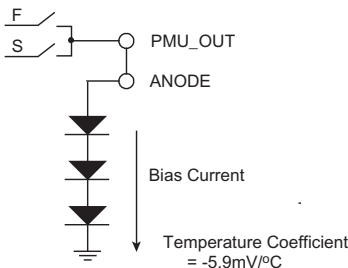
PUV is a single input and is buffered at each channel to the pull-up resistors. The buffer and resistor are capable of sourcing or sinking (pull-up or pull-down) currents for 0 to 5V external signals.

Thermal Monitor

An on-chip thermal diode string of three diodes in series allows accurate die temperature measurements (see diagram below).

A bias current of 100 µA is injected through the string, and the measured voltage corresponds to a specific junction temperature with the following equation:

$$T_j [^\circ C] = (0.7195 - V_{ANODE}/3) / (0.001967)$$

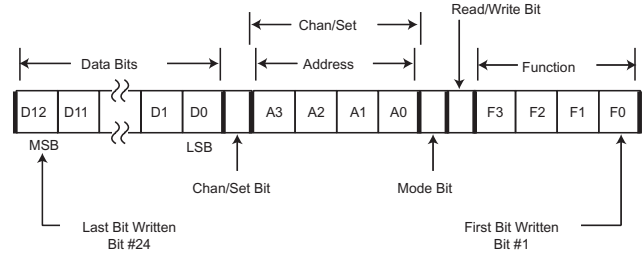


The ANODE of the diodes may be switched internally to the EPMU bus such that temperature measurements can be performed by the EPMU. The connection to the diode string's ANODE pin for the EPMU is performed externally by shorting the PMU_OUT pin to the ANODE pin. This external connection is available to make it possible to access the diode string when the device is not powered up. This is useful for calibration purposes of the diode string. The ANODE pin is internally ESD protected in the positive direction to VXX. To use the diode string, VXX needs to either be floating (unpowered operation) or ≥2V.

Programming Functional Description

The E7804 features a serial data input programming structure to program the channels functions and switches, assign or invoke Set functions, as well as control more global chip functions such as Reset and Calibration. The majority of the functions are both Read and Write. The serial streams are all 24-bits long and are referred to as "instructions" because the serial streams are built up with address, function, read and select bits as well as data into the 24-bit stream which is clocked serially into the device.

The following is a description of the 24-bit instruction stream.



Data: 13 bits

This field contains the data to be written into various registers which control the function of the part, or the selected channel(s).

Channel/Set Address Select: 1 bit

This bit determines whether a single channel or a set of channels is being addressed.

- 0 = channel direct functions
- 1 = set of channels

Channel/Set Address: 4 bits

This field contains the address of the channel or set being operated on.

Mode: 1 bit

This determines whether the instruction refers to a chip-level control (such as chip reset), or refers to a channel or set of channels.

- 0 = chip function
- 1 = channel or set function

TEST AND MEASUREMENT PRODUCTS

Circuit Description (continued)

Read/Write: 1 bit

This determines whether a particular address/function is being written or read. (Note that some functions are read-only or write-only).

- 0 = write a control/data register
- 1 = read back the contents of a register

Function: 4 bits

This determines which function within a channel or set is being set or read.

Refer to Figure 2 for a block diagram of the Write and Read logic for the serial programming. The serial data is input into the device SDIN pin. The data at SDIN is clocked in on the high-going edge of the CLKIN input signal. The data at the SDOUT pin is clocked out on the low-going edge of the CLKIN input signal for ease of “daisy chaining” multiple devices.

RESET*

There is a single input pin to the entire E7804 chip that will clear all on-chip registers and open all on-chip switches. This input pin, RESET*, is active low and is asynchronous, not requiring any CLKIN transitions to operate. It is advised that, upon power-up in a system, this pin is either held low or cycled low for a brief time while the system and power

supplies become stable in order to put the E7804 into a known starting state. After power-up, the RESET* may be exercised or a soft reset instruction may be programmed.

Write Serial Data

Data is shifted into the WRITE shift register using CLKIN. The data stored in the shift register will be stored into the E7804 by asserting the LOAD input signal during the 24th CLKIN high-going edge. The LATCH will hold the instruction inside the E7804 for address decoding and data storage into the appropriate on-chip registers. **Seven (7) more CLKIN high-going edges should be given after a LOAD for full decode and all instruction executions.**

Refer to Figure 3 for a timing diagram of the writing operation. Notice that the SDOUT data that is clocked out on the low-going edge of CLKIN is a bit for bit representation of the data that had been shifted into the E7804 24 clock edges beforehand. This echoing of the data allows the user to “daisy chain” multiple E7804 devices to minimize the number of serial data streams that need to be implemented. The compromise is the length of time it takes to clock through all the 24-bit instructions for all the devices in the chain.

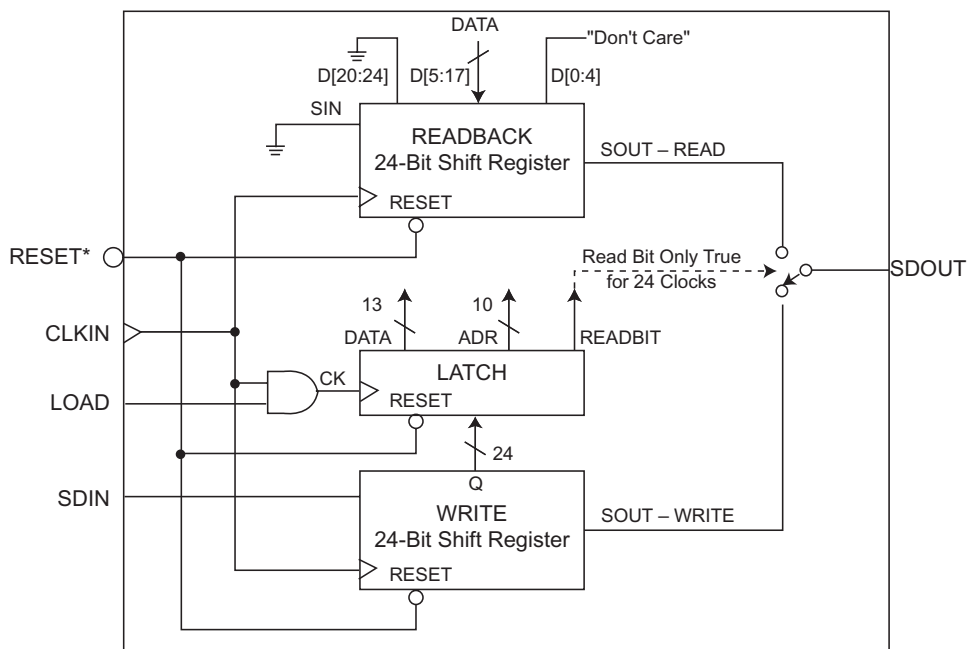


Figure 2. Block Diagram of Read and Write Shift Registers

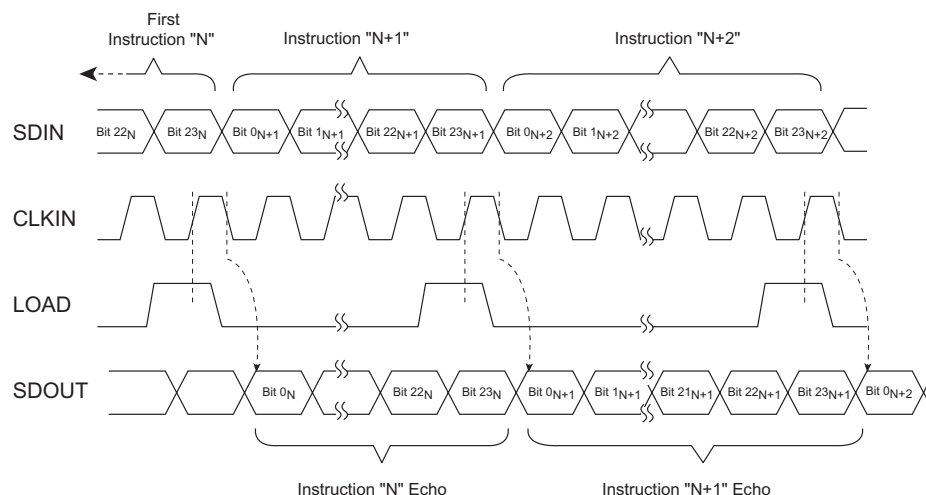


Figure 3. Serial Data Programming - Write Instruction

Figure 4 depicts two topologies to serially read and write multiple E7804 devices on a single assembly. Figure 4a daisy chains the serial I/O (SDOUT to SDIN) pins, and the CLKIN and LOAD functions are common for all the E7804s. This topology uses a minimum amount of I/O from the control logic. However, in order to read or write the E7804's an instruction string of 24 x N bits long needs to be created, clocked all the way through the devices, and a parallel LOAD signal asserted for all devices. NO_OP instructions may be used for the devices that are not being addressed.

Figure 4b shows a topology from the control logic that offers rapid programming time and complete independence. This topology relies on enough I/O signals being available from the control logic. Notice that the CLKIN pins are still all common because independence is allowed by the individual LOAD signals to each E7804.

If it is determined that readback from the E7804s are not necessary, the control logic can be further simplified. Readback is not necessary for the operation of the E7804. It is offered as a good diagnostic tool and possible programming aid.

Read Serial Data

In order to readback data, an instruction is constructed with the Read_Bit set to a logical "1" in the instruction

stream and written to the E7804. The instruction stream must be properly constructed for address and select bits to insure that the proper register will be accessed for readback. The data bits D0:D12 in this Read instruction are Don't_Care.

Refer to Figure 5 for a timing diagram of the readback process and Figure 2 for a block diagram of how the readback operation works. Once the LOAD signal is asserted on the 24th high-going CLKIN edge to latch in the READ instruction for a particular address, the internal READ line will assert true and switch the SDOUT pin to output data from the internal readback shift register. The readback data will immediately start to output from the SDOUT pin on the low-going edge of CLKIN. The readback will continue for 24 bits.

The first 5 bits of data readback should be ignored. The next 13 bits will be the requested register's readback data. Finally, the last 6 bits are logical zeros.

While clocking out the readback data, a new instruction can be simultaneously clocked in at SDIN. At the conclusion of the 24-bit readback, the SDOUT data will revert back to echoing the SDIN data shifted by 24 clocks.

TEST AND MEASUREMENT PRODUCTS
 Circuit Description (continued)

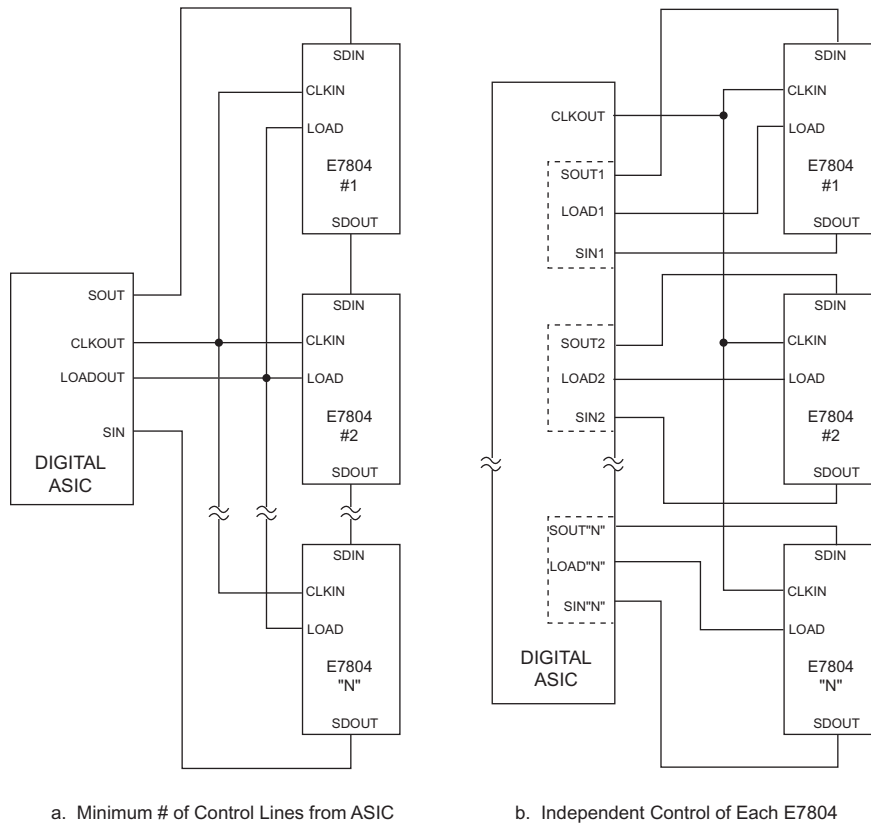


Figure 4. Serial Control of Multiple E7804s

Figure 5 depicts the conclusion of a Read instruction being written to the E7804. The first LOAD pulse straddling the rising edge of CLKIN latches in the Read instruction, echoing at SDOUT stops, and the readback of the register begins. After 24 low-going clocks, the data at SDOUT resumes echoing the written data at SDIN. Even without the second LOAD pulse, the echoing will begin. Figure 5 depicts a Write instruction following the Read. This could be another Read instruction, in which case the echoing of SDIN would not begin as indicated. Instead, another sequence of 24 readback bits would begin.

The readback data format and address are defined in Table 3. The Read operation will continue for 24 low-going clock edges. The SDOUT will begin outputting data from the write shift register after the 24th low-going clock edge.

Address Map

Table 2 shows the Write Table and Address Map. Across the top of the table are the 24 bits of data denoted as Bit #0 through Bit #23. Hex notation is also provided as well as the binary positions.

The instruction is constructed of 13 Data bits, 8 address bits, 2 select bits and a read bit. Figure 3 shows the bit pattern in the write instructions. The instructions are separated into 3 main groups. The Chip Functions, the Channel Functions and the Set Functions. Each instruction has a Register Name associated with it. In the pages following Table 2 are descriptions of each of the register names and, where applicable, a bit-by-bit description of the data.

Chip Functions

The Chip Functions group of instructions controls chip functions that are global in scope and not associated with a particular channel. Examples of these functions are the chip identification number and revision, the Reset function for chip wide reset, and initiation of calibration.

Function Address – Instructions in the group are denoted by this set of bits.

Read Bit – Set to “1” only if user intends to read back a register.

Chan Bit – Set to a “0” since this instruction group is not channel related.

Chan/Set Adr – These 4 bits are “don’t care”. Since these would select either a channel or set number, and these are Chip Functions, they don’t apply.

Set Select Bit – This bit is a “don’t care” for the Chip Functions group.

Channel Functions

The Channel Functions group of instructions address the functionality of individual registers and bits that are particular to specific channels of the E7804. Driver states, channel switches, calibration factors and set assignments are included in this group.

Function Address – These bits denote which function of the particular channels is being addressed.

Read Bit – Set to “1” only if user intends to read back a register.

Chan Bit – Set to a “1” because these instructions relate to specific channel registers.

Chan/Set Adr – These bits will denote which channel is being addressed for the particular function. Valid range is 0x0 through 0x3 for the E7804.

Set Select Bit – This bit is set to a “0” because this is the Channel Functions group.

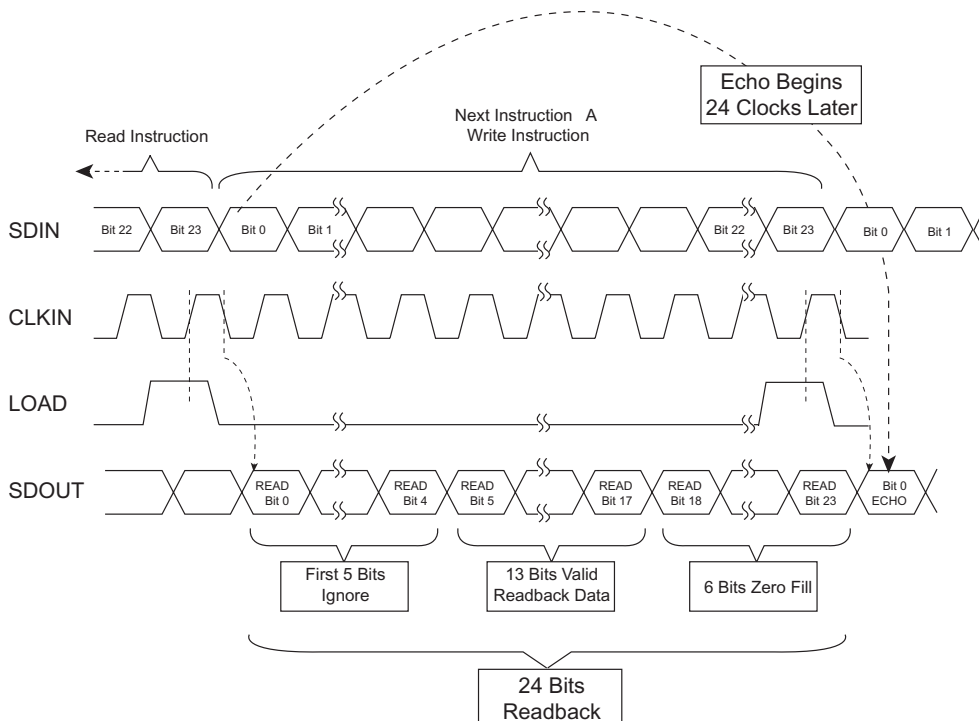


Figure 5. Serial Data Programming - Readback Sequence

TEST AND MEASUREMENT PRODUCTS

Circuit Description (continued)

Set Functions

Set Functions are a group of 8 instructions corresponding to the 8 available Sets that will configure any channel that has been assigned to that Set. The Set Functions are write-only, but the effects of a Set instruction can be read back from the individual channel's registers. The Set is given control of any channel's driver states or switches. The Set concept is a way of programming all channels on any E7804 that have been assigned to that particular SET to a particular configuration with one instruction write cycle.

Function Address – These addresses should all be “0”.

Read Bit – Set to “0” since there is no readback for set instructions.

Chan Bit – Set to a “1”.

Chan/Set Adr – These bits will denote which set is being programmed. Valid set values are 0x0 through 0x7 corresponding to the eight valid SETs.

Set Select Bit – This bit is a “1” because this is the SET Functions group.

SET Programming

Referring to Table 2, a channel's SETs Register may be programmed via the CH[0:3]_set_assign instructions. This is an independent 8-bit register per channel which determines the SETs to which the channel belongs. A channel may belong to none, one, or any combination of up to 8 sets.

Programming the Driver's Source Impedance

Figure 1 shows that each driver's source impedance is programmable over a 48W to 110W range so as to match the impedance of the transmission line connecting VOP to the Device Under Test (DUT). The driver's source impedance is automatically programmed to match $R_{REF}/100$, where R_{REF} is the external reference resistor connected to the EREF pin.

Initiating the source match auto-calibration sequence is a “chip function” (Table 2). Auto-calibration is performed on all channels in parallel.

The Driver's source impedance is affected by its DVH and DVL levels and, therefore, auto-calibration should be initiated whenever driver levels are changed.

Following auto-calibration, a driver's source impedances match ($R_{REF}/100$) W when its output is at $(DVH + DVL) / 2$. If the output voltages of the driver are reprogrammed, then it is advised to recalibrate to maintain the best accuracy.

Calibration will occur after writing the global function instruction `calibrate_output_z`. Calibration requires an additional 576 clock edges from CLKIN to complete the process. This is 24 instructions worth of clocks. Instructions for the device undergoing calibration may be any valid instruction except that which connects the CTC output to POUT, or simply applying the clocks without LOAD'ing instructions is also valid. At the end of the process, the new, calibrated output impedances will be applied to the driver output stage. The driver may be in the enabled or disabled state. If enabled, there could be a noticeable perturbation on the output.

TEST AND MEASUREMENT PRODUCTS
Circuit Description (continued)
Chip Functions

Register Name <i>no_op</i>	Function Address 0x00 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 0 Mode Write Only
Default Value 0 0000 0000 0000	0x00	
Description	This bit stream is used as a null stream. No operation will result if shifted in and a LOAD is executed. It is useful if multiple devices are connected in serial arrangement and a chip is not being addressed, but a parallel LOAD will occur for all devices on the serial bus.	
Register Name <i>chip_id</i>	Function Address 0x01 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Read Only
Default Value 1 1110 0111 1100	0x1E7C	
Description	This identifies the device part number, decimal equivalent is 7804. It is a read only register.	
Register Name <i>chip_revision</i>	Function Address 0x02 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Read Only
Default Value 0 0000 0000 0000		
Description	This identifies the device die revision number. The first revision is decimal 0, the second will be decimal 1, etc. It is a read only register.	
Register Name <i>calibrate_output_z</i>	Function Address 0x03 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Read/Write
Default Value 0 0000 0000 0000	0x00	
Description	Writing to the LSB of this address will initiate a chip-wide calibration of the output impedances of the drivers. The internal state machine that performs the calibrations will require 21 microseconds for complete calibration of all channels. This is 30 instructions (x24 clocks) clocked at 33 MHz CLKIN. Because the calibration and Continuity Test Circuits (CTC) both share the EREF pin, z calibration cannot occur if any CTC is switched into operation using S5. D0 – writing a one to this bit will initiate the calibration process. Once calibration is completed, this bit will readback as a 0.	
Register Name <i>chip_switches</i>	Function Address 0x04 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Read/Write
Default Value 0 0000 0000 0000	0x00	
Description	This register is used to switch non-channel specific switches. D0 – writing a one to this bit will close the S7 switch. The S7 switch is a dual pole switch that connects the EPMUS and EPMUF signals to the PMU_OUT pin. The primary use is when PMU_OUT is externally shorted to the temperature diode ANODE pin. Closing this switch will allow the external PMU to connect to the temperature diode string on an individual E7804 to perform die temperature measurements.	
Register Name <i>global_calib_factor</i>	Function Address 0x05 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Read/Write
Default Value 0 0000 1111 1111	0x00	
Description	This register holds the eight-bit calibration factor based upon the resistor value on the EREF pin. The value in this register is used in calculating the output impedances of the driver outputs during calibration. After RESET it will be 0xFF. D0-D7 – the eight-bit value of the calibration factor. D0=LSB.	
Register Name <i>diagnostic</i>	Function Address 0x06 Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Read/Write
Default Value 0 0000 0000 0000	0x00	
Description	This register is used for test access. Do not write to this register.	
Register Name <i>reset</i>	Function Address 0x0F Channel/Set Address don't care Channel Select Bit 0	Set Select Bit 0 or 1 Mode Write Only
Default Value 0 0000 0000 0000	0x00	
Description	This register is used for programmable (soft) reset of the device. D0 – ALL – writing a one to this bit will perform a soft reset of the entire chip. It is wire OR'd with the external RESET* pin. The ALL reset function requires 7 clock cycles after this bit is latched in by the LOAD signal. The RESET ALL instruction will clear the SDIN and SDOUT shift registers. It is advised to follow a RESET ALL instruction with a NO_OP instruction. D1 – SETS – writing a one to this bit will perform a soft reset of all the set assignments for all the channels of the device. This SET function function requires 5 clock cycles after this bit is latched in by the LOAD signal.	

TEST AND MEASUREMENT PRODUCTS

Circuit Description (continued)

Channel Functions

Channel Relay and States Registers			
Register Name	<i>CH0_switches_&_states</i>	Function Address 0x00 Channel/Set Address 0x00 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	<p>This register is used for controlling the Channel_0 (CH0) switches. Bits are also present to control the CH0 driver state and read back the states of the CH0 comparator outputs. The comparator output states are indicated above as unknown unless the input voltage relationships are known.</p> <p><u>D0 – S1</u> – writing a one to this bit will close the switch that connects the driver output to the channels VIO pin.</p> <p><u>D1 – S2</u> – writing a one to this bit will close the switch that connects the window comparator input to the channel's VIO pin.</p> <p><u>D2 – S3</u> – writing a one to this bit will close the switch that connects the driver output to the external PMU sense line (EPMUS) for purposes of system diagnostics.</p> <p><u>D3 – S4</u> – writing a one to this bit will close the switches that connect both the external PMU bus sense (EPMUS) and force (EPMUF) lines to the channel's POUT pin.</p> <p><u>D4 – S5</u> – writing a one to this bit will close the switch that connects the continuity test circuit (CTC) to the channel's POUT pin. If any channel has S5 closed, then output impedance calibration cannot occur.</p> <p><u>D5 – S6</u> – writing a one to this bit will close the switch that connects the pull-up resistor and voltage to the channel's POUT pin.</p> <p><u>D6 – SDHI</u> (Serial Data Hi) – writing a logical one to this bit will force the channel's driver to output the DVH voltage. Writing a zero to this bit will force the driver to output the DVL voltage. The SDHI bit will only have effect if the SEN bit (D8) in this register is set to a logical one, allowing the SDHI bit to override the state of the external DHI signal to this channel's driver.</p> <p><u>D7 – SDEN</u> (Serial Data Enable) – writing a logical one to this bit will enable the channel's driver to output either DVH or DVL (based on the SDHI bit). Writing a zero to this bit disables the driver output to high impedance. The SDEN bit will only have effect if the SEN bit (D8) in this register is set to a logical 1, allowing the SDEN bit to override the state of the external DEN signal to this channel's driver.</p> <p><u>D8 – SEN</u> (Serial Enable) – writing this bit to a logical one will allow the D6 and D7 bits in this register override the external driver control signals DHI and DEN.</p> <p><u>D9 – QB</u> – this bit is a Read Only bit that is the state of the channel's comparator B output. Writing to this bit will have no effect.</p> <p><u>D10 – QA</u> – this bit is a Read Only bit that is the state of the channel's comparator A output. Writing to this bit will have no effect.</p>		
Register Name	<i>CH1_switches_&_states</i>	Function Address 0x00 Channel/Set Address 0x01 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	<p>This register is used for controlling the Channel_1 (CH1) switches. Bits are also present to control the CH1 driver state and read back the states of the CH1 comparator outputs. See the bit definitions above for the CH0_relay_&_switches register.</p>		
Register Name	<i>CH2_switches_&_states</i>	Function Address 0x00 Channel/Set Address 0x02 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000		
Description	<p>This register is used for controlling the Channel 2 (CH2) switches. Bits are also present to control the CH2 driver state and read back the states of the CH2 comparator outputs. See the bit definitions above for the CH0_relay_&_switches register.</p>		
Register Name	<i>CH3_switches_&_states</i>	Function Address 0x00 Channel/Set Address 0x03 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	<p>This register is used for controlling the Channel 3 (CH3) switches. Bits are also present to control the CH3 driver state and read back the states of the CH3 comparator outputs. See the bit definitions above for the CH0_relay_&_switches register.</p>		

Circuit Description (continued)
Channel Functions (continued)

Channel Calibration Registers _ DVH			
Register Name	<i>CH0_DVH_calib_z</i>	Function Address 0x01 Channel/Set Address 0x00 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH0's driver impedance to DVH. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Register Name	<i>CH1_DVH_calib_z</i>	Function Address 0x01 Channel/Set Address 0x01 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH1's driver impedance to DVH. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Register Name	<i>CH2_DVH_calib_z</i>	Function Address 0x01 Channel/Set Address 0x02 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000		
Description	This register is used to store the calibration 8-bit code for CH2's driver impedance to DVH. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Register Name	<i>CH3_DVH_calib_z</i>	Function Address 0x01 Channel/Set Address 0x03 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH3's driver impedance to DVH. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Channel Calibration Registers _ DVL			
Register Name	<i>CH0_DVL_calib_z</i>	Function Address 0x01 Channel/Set Address 0x00 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH0's driver impedance to DVL. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Register Name	<i>CH1_DVL_calib_z</i>	Function Address 0x01 Channel/Set Address 0x01 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH1's driver impedance to DVL. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Register Name	<i>CH2_DVL_calib_z</i>	Function Address 0x01 Channel/Set Address 0x02 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH2's driver impedance to DVL. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		
Register Name	<i>CH3_DVL_calib_z</i>	Function Address 0x01 Channel/Set Address 0x03 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write
Default Value	0 0000 0000 0000 0x00		
Description	This register is used to store the calibration 8-bit code for CH3's driver impedance to DVL. Data is written internally after a chipwide calibration of the output impedances has occurred. User can read back this data or write different data into the register.		

TEST AND MEASUREMENT PRODUCTS
Circuit Description (continued)
Channel Functions (continued)

Channel Set Assignment Registers																					
Register Name <i>CH0_set_assign</i>	Function Address 0x01 Channel/Set Address 0x00 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write																			
Default Value	0 0000 0000 0000 0x00																				
Description	This register is used to assign CH0 to any or no "SETS". A logical 1 in the bit position will assign CH0 to respond to global commands for the corresponding set.																				
	<table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Bit #</th> <th>D7</th> <th>D6</th> <th>D5</th> <th>D4</th> <th>D3</th> <th>D2</th> <th>D1</th> <th>D0</th> </tr> </thead> <tbody> <tr> <td></td> <td>set7</td> <td>set6</td> <td>set5</td> <td>set4</td> <td>set3</td> <td>set2</td> <td>set1</td> <td>set0</td> </tr> </tbody> </table>			Bit #	D7	D6	D5	D4	D3	D2	D1	D0		set7	set6	set5	set4	set3	set2	set1	set0
Bit #	D7	D6	D5	D4	D3	D2	D1	D0													
	set7	set6	set5	set4	set3	set2	set1	set0													
Register Name <i>CH1_set_assign</i>	Function Address 0x01 Channel/Set Address 0x01 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write																			
Default Value	0 0000 0000 0000 0x00																				
Description	This register is used to assign CH1 to any or no "SETS". A logical 1 in the bit position will assign CH0 to respond to global commands for the corresponding set. See bit positions in CH0_set assign register description above.																				
Register Name <i>CH2_set_assign</i>	Function Address 0x01 Channel/Set Address 0x02 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write																			
Default Value	0 0000 0000 0000 0x00																				
Description	This register is used to assign CH2 to any or no "SETS". A logical 1 in the bit position will assign CH0 to respond to global commands for the corresponding set. See bit positions in CH0_set assign register description above.																				
Register Name <i>CH3_set_assign</i>	Function Address 0x01 Channel/Set Address 0x03 Channel Select Bit 1	Set Select Bit 0 Mode Read/Write																			
Default Value	0 0000 0000 0000 0x00																				
Description	This register is used to assign CH3 to any or no "SETS". A logical 1 in the bit position will assign CH0 to respond to global commands for the corresponding set. See bit positions in CH0_set assign register description above.																				

TEST AND MEASUREMENT PRODUCTS
Circuit Description (continued)
Set Functions

Register Name	<i>Set0_switches_&_states</i>	Function Address	0x00	Set Select Bit	1
		Channel/Set Address	0x00	Mode	Write Only
		Channel Select Bit	1		
Default Value	0 0000 0000 0000		0x00		
Description	<p>This register is used for controlling the Set_0 (CH0) switches on any channel that has been assigned to Set_0. Bits are also present to control the channels' driver states.</p> <p><u>D0 – S1</u> – writing a one to this bit will close the switch that connects the driver output to the channel's VIO pin.</p> <p><u>D1 – S2</u> – writing a one to this bit will close the switch that connects the window comparator input to the channel's VIO pin.</p> <p><u>D2 – S3</u> – writing a one to this bit will close the switch that connects the driver output to the external PMU sense line (EPMUS) for purposes of system diagnostics.</p> <p><u>D3 – S4</u> – writing a one to this bit will close the switches that connect both the external PMU bus sense (EPMUS) and force (EPMUF) lines to the channel's POUT pin.</p> <p><u>D4 – S5</u> – writing a one to this bit will close the switch that connects the continuity test circuit (CTC) to the channel's POUT pin.</p> <p><u>D5 – S6</u> – writing a one to this bit will close the switch that connects the pull-up resistor and voltage to the channel's POUT pin.</p> <p><u>D6 – SDHI</u> (Serial Data Hi) – writing a logical one to this bit will force the channel's driver to output the DVH voltage. Writing a zero to this bit will force the driver to output the DVL voltage. The SDHI bit will only have effect if the SEN bit (D8) in this register is set to a logical one, allowing the SDHI bit to override the state of the external DHI signal to this channel's driver.</p> <p><u>D7 – SDEN</u> (Serial Data Enable) – writing a logical one to this bit will enable the channel's driver to output either DVH or DVL (based on the SDHI bit). Writing a zero to this bit disables the driver output to high impedance. The SDEN bit will only have effect if the SEN bit (D8) in this register is set to a logical 1, allowing the SDEN bit to override the state of the external DEN signal to this channel's driver.</p> <p><u>D8 – SEN</u> (Serial Enable) – writing this bit to a logical one will allow the D6 and D7 bits in this register override the external driver control signals DHI and DEN.</p>				
Register Name	<i>Set1_switches_&_states</i>	Function Address	0x00	Set Select Bit	1
		Channel/Set Address	0x01	Mode	Write Only
		Channel Select Bit	1		
Default Value	0 0000 0000 0000		0x00		
Description	<p>This register is used for controlling the Set_0 (CH0) switches on any channel that has been assigned to Set_1. Bits are also present to control the channels' driver states. See the bit definitions to the <i>Set0_relays_&_states</i> for bit definitions.</p>				
Sets 2 through 6					
Register Name	<i>Set7_switches_&_states</i>	Function Address	0x00	Set Select Bit	1
		Channel/Set Address	0x01	Mode	Write Only
		Channel Select Bit	1		
Default Value	0 0000 0000 0000		0x00		
Description	<p>This register is used for controlling the Set_7 (CH0) switches on any channel that has been assigned to Set_7. Bits are also present to control the channels' driver states. See the bit definitions to the <i>Set0_relays_&_states</i> for bit definitions.</p>				

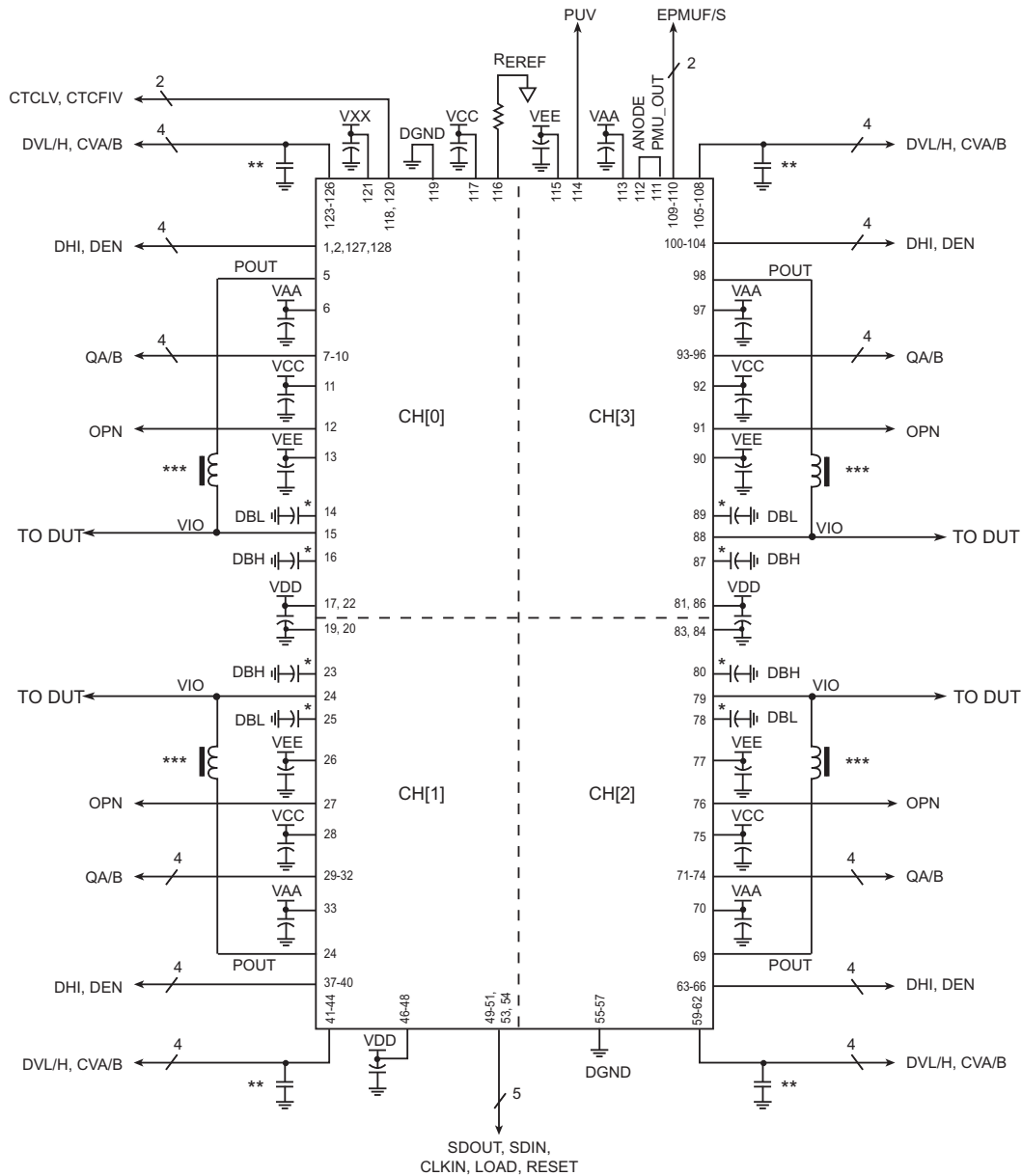


Figure 6. E7804 Hookup

VEEs of all Channels must be connected together; same for VCCs, VAAs, VDD and GNDs.

NOTE: All capacitors are 0.1 μ F unless otherwise noted.

*DBH/L capacitors are 0.47 μ F.

**DVH/L each have 0.22 μ F capacitors. Not necessary for CVA/B.

***Two ferrites in series. Each 600 Ω ; 1206 and 0603 package sizes. Steward Part #MI0603J601R-00 and #MI1206K601R-00. See text for further explanation.

Low Cost Pin Electronics with the E7804

Figure 7 shows 16 channels of 'Low Cost' Pin Electronics featuring the E7804, E6435 (Level DACs) and E4287 (PMU).

- 16 channels with levels per-pin and shared PMU per 16 pins
- 133 MHz clocks
- PMU, -3.25V, +9.75V with 4 current ranges to $\pm 40\text{mA}$
- Continuity test per pin
- Per-pin pull-up resistor
- Compatible Power (common) supply (VCC, VDD, VEE, etc.) requirements for each chip

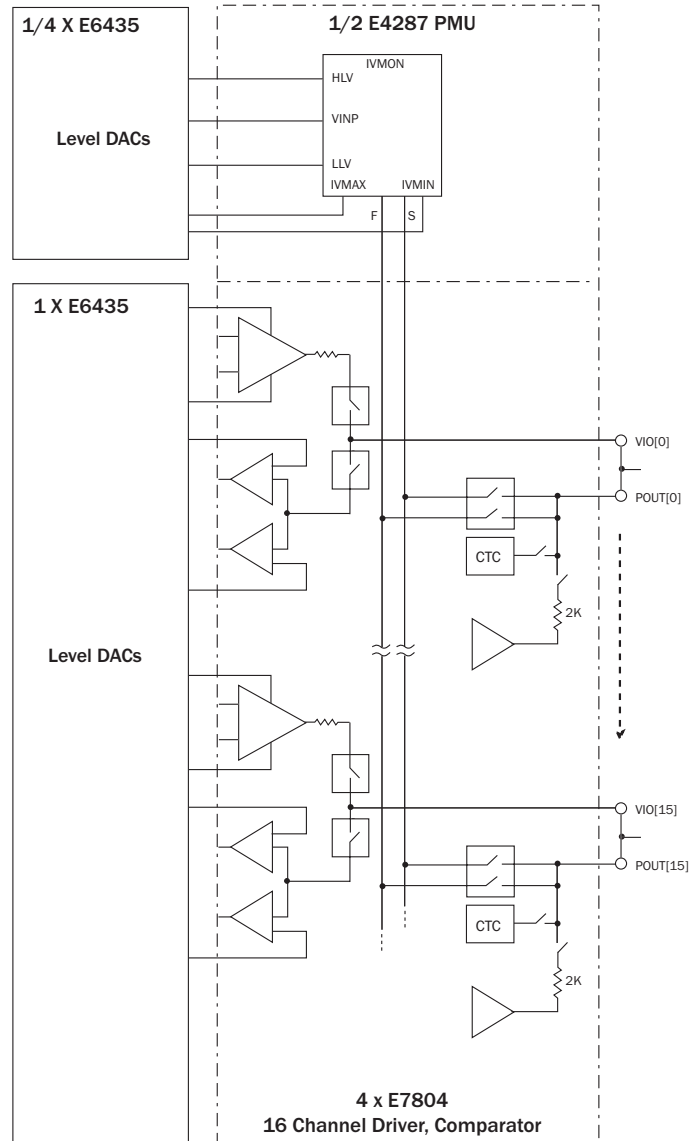


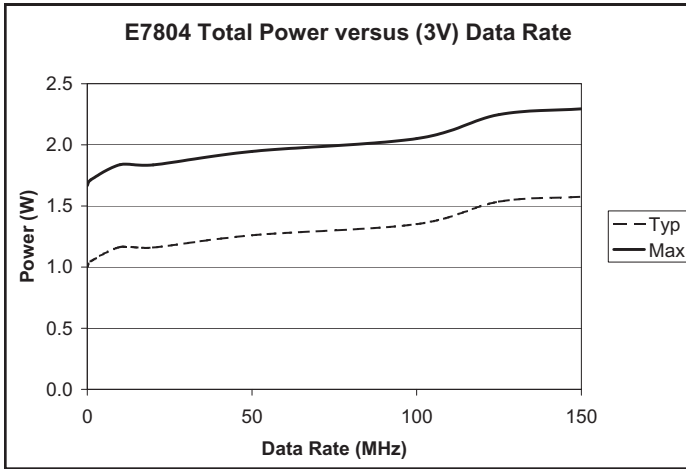
Figure 7. "Low Cost", 16 Channel Pin Electronics

TEST AND MEASUREMENT PRODUCTS

Application Information (continued)

Computing Maximum Power Consumption

The diagram below shows the power consumption of the E7804 as a function of clocking frequency of all channels.



The power consumption goes up with frequency and output voltage swing.

Cooling Considerations

Depending on the maximum operating frequencies and voltage swings the E7804 will need to drive, it may require the use of heatsinking to keep the maximum die junction temperature within a safe range and below the specified maximum of 100½C.

The E7804 package has an internal heatspreader located at the top side of the package to efficiently conduct heat away from the die to the package top. The thermal resistance of the package to the top is the qJC (junction-to-case) and is specified at 4½C/Watt.

In order to calculate what type of heatsinking should be applied to the E7804, the designer needs to determine the worst case power dissipation of the device in the application. The graph above gives a good visual relationship of the power dissipation to the maximum operating frequency (all channels simultaneously) and driver output voltage swings. Another variable that needs to be determined is the maximum ambient air temperature that will be surrounding or blowing on the device and/or the heatsink

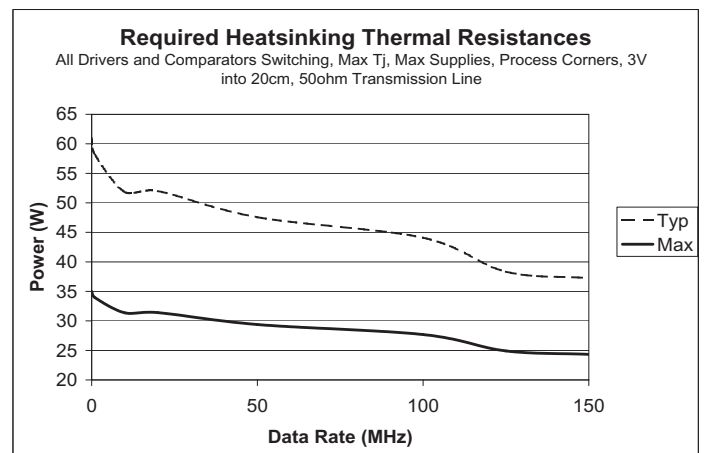
system in the application (assuming an air cooled system). A heatsinking solution should be chosen to be at or below a certain thermal impedance known as Rq in units of °C/Watt. The heatsinking system is a combination of factors including the actual heatsink chosen and the selection of the interface material between the E7804 and the heatsink itself. This could be thermal grease or thermal epoxy, and they also have their own thermal impedances. The heatsinking solution will also depend on the volume of air passing over the heatsink and at what angle the air is impacting the heatsink. There are many options available in selecting a heatsinking system. The formula below shows how to calculate the required maximum thermal impedance for the entire heatsink system. Once this is known, the designer can evaluate the options that best fit the system design and meet the required Rθ.

$$R\theta(\text{heatsink_system}) = (TJ_{max} - T_{ambient} - P * \theta_{JC}) / P$$

where,

- R (heatsink_system) is the thermal resistance of the entire heatsink system
- TJmax is the maximum die temperature (100 °C)
- Tambient is the maximum ambient air temp expected at the heatsink (°C)
- P is the maximum expected power dissipation of the E7804 (Watts)
- θJC is the thermal impedance of the E7804 junction to case (4 °C/W)

The graph below uses the power estimates from the previous graph and indicates the required maximum thermal impedances required for the heatsinking system using the above formula with Tambient at 35 °C.



The value of the thermal resistance of the E7804 package

TEST AND MEASUREMENT PRODUCTS

Application Information (continued)

junction to air with 400 linear feet per minute (LFPM) of airflow is specified at 22 °C/W. At operating points greater than or equal to this value, no additional heatsinking is needed to keep the die temperatures below the maximum 100 °C as long as the ambient temperature of the 400 LFPM air does not exceed 35 °C.

More information on heatsink system selections can be read on heatsink vendors' web sites and in the Semtech Application Note #ATE-A2 Cooling High Power, High Density Pin Electronics.

Protection Considerations

The E7804 has ESD protection on its input and outputs.

The E7804 has internal, high voltage, disconnect switches for VIO and POUT pins. When open, these provide protection against voltages input into VIO and POUT which might have damaged drivers, comparators, and other internal circuits.

Power Supply Sequencing/Latch-Up Protection

In order to avoid the possibility of latch-up when powering this part up (or down), be careful that the conditions listed in the Absolute Maximum Ratings are never violated. That is, the power supplies should never be reverse-polarity with respect to ground, and the input signals should never go beyond the power supply rails.

Furthermore, the lower-voltage analog supplies should never be greater than the higher-voltage supplies (VAA < VCC < VXX). This can easily be implemented by utilizing the diode circuit depicted in Figure 14 for each PCB that has E7804 devices on it. The following conditions must be met at all times during power-up and power-down.

1. VEE GND VAA VCC VXX
2. GND VDD VCC
3. VEE Analog Inputs VCC or VXX
4. GND Digital Inputs VDD

The following sequencing can be used as a guideline when powering up:

- | | | | |
|----|-----|----|----------------|
| 1. | VEE | 5. | VDD |
| 2. | VXX | 6. | Digital Inputs |
| 3. | VCC | 7. | Analog Inputs |
| 4. | VAA | | |

The recommended power-down sequence is the reverse order of the power-up sequence.

One approach to ensure that the power supply polarities do not become reversed is to use Schottky diodes, as shown in Figure 8. One set of these diodes should be used per board. The optimum type of Schottky will depend on how much current the power supplies can source.

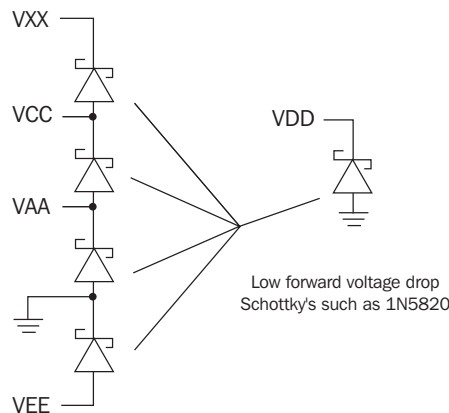
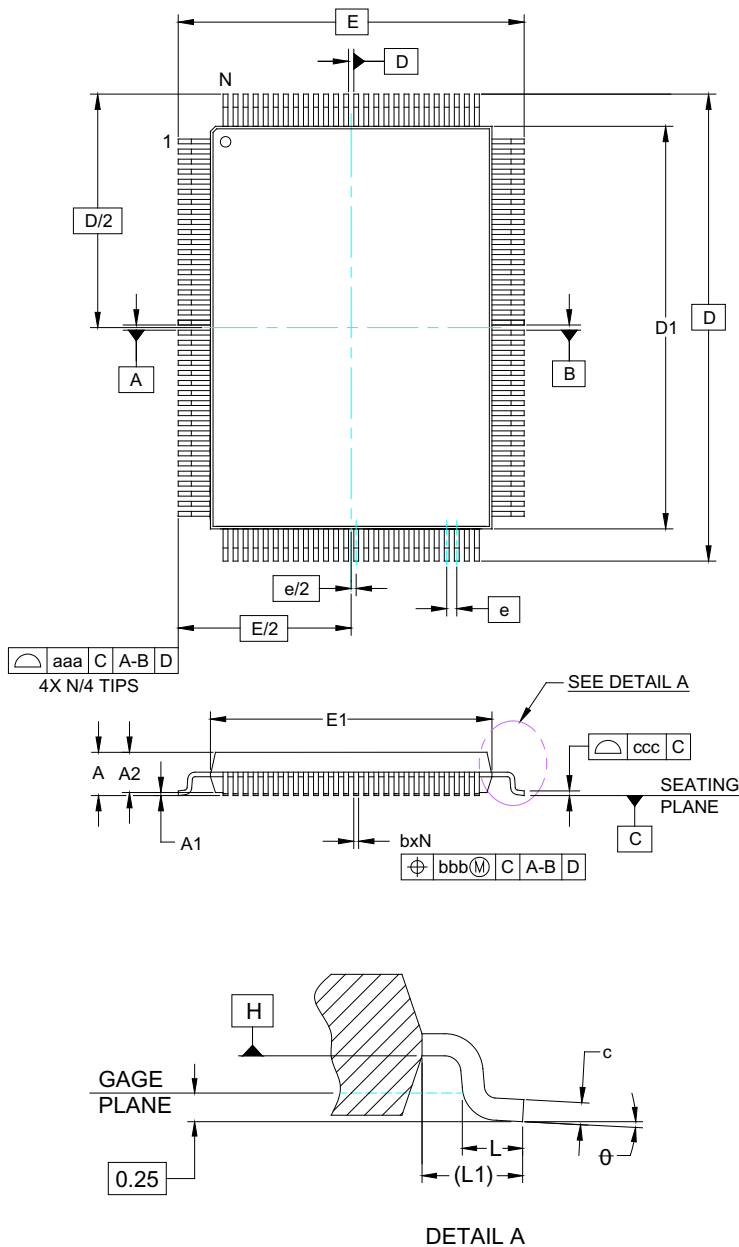


Figure 8. Board Level Supply Diodes

TEST AND MEASUREMENT PRODUCTS
Package Information

128-Pin MQFP
 14mm x 20mm x 2mm
 (with Internal Heat Spreader)



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	.093	-	-	2.35
A1	.000	-	.010	0.00	-	0.25
A2	.075	.079	.083	1.90	2.00	2.10
b	.007	-	.011	0.19	-	0.27
c	.004	-	.009	0.11	-	0.23
D	.913 BSC			23.20 BSC		
D1	.783	.787	.791	19.90	20.00	20.10
E	.677 BSC			17.20 BSC		
E1	.547	.551	.555	13.90	14.00	14.10
e	.020 BSC			0.50 BSC		
L	.029	.035	.041	0.73	0.88	1.03
L1	(.063)			(1.60)		
R	.095	.115	.135	2.42	2.92	3.42
N	128			128		
ND	38			38		
N	26			26		
θ	0-7°			0-7°		
aaa	.008			0.20		
bbb	.003			0.08		
ccc	.003			0.08		

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DATUMS **-A-**, **-B-** AND **-D-** TO BE DETERMINED AT DATUM PLANE **-H-**.
3. DIMENSIONS "E1" AND "D1" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

TEST AND MEASUREMENT PRODUCTS

Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Units
Positive Analog Supply – VCC or VXX	VCC, VXX	-0.5	VEE + 16	V
Positive Analog Supply – VAA	VAA	-0.5	6.0	V
Negative Analog Supply – VEE	VEE	-5.5	0.5	V
Digital Power Supplies – VDD	VDD	-0.5	6.0	V
Total Power Supply Ranges	VCC to VEE	-0.5	16.0	V
	VCC to VAA	-0.5	16.0	V
Digital Input Voltages	SDIN, CLKIN, LOAD, RESET*, OPN	DGND - 0.5	VDD + 0.5	V
Driver/Comparator Pin	VIO	VEE	VCC	V
Comparator Only Connected	VIO	CVL - 6	CVH + 6	V
Driver Connected	VIO	DVL - 0.7	DVH + 0.7	V
Parametric Pin				
CTC and PUV not Connected	POUT	VEE	VXX	V
CTC Connected	POUT	VEE	VAA	V
PUV Connected	POUT	0	VAA	V
Storage Temperature	TS	-65	150	°C
Junction Temperature	TJ		125	°C
Soldering Temperature (5 seconds, .25" from the pin)	TSOL		260	°C

Stresses above those listed in “Absolute Maximum Ratings” section may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these, or any other conditions beyond those listed, is not implied. Exposure to absolute maximum conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Units
Positive Analog Supply to Switches	VXX to AGND	VCC	9.5	VEE + 15.0	V
Positive Analog Power Supply – Channels	VCC to AGND	8	8.25	8.5	V
Positive Analog Power Supply – Channels	VAA to AGND	4.75	5	5.5	V
Negative Power Supply – Channels	VEE to AGND	-5.25	-5	-4.75	V
Total Analog Supply Range	VCC to VEE	12.75		13.75	V
Digital, Logic Power Supplies	VDD to DGND	3.13	3.3	3.46	V
Thermal Resistance - Junction to Case (Top)	θ_{JC}		4		°C/W
Thermal Resistance - Junction to Ambient					
Still Air	θ_{JA}		28		°C/W
100 lfpm	θ_{JA}		25.2		°C/W
400 lfpm	θ_{JA}		22.1		°C/W
Junction Temperature	TJ	25		100	°C

Note: AGND and DGND must be connected together externally.

TEST AND MEASUREMENT PRODUCTS
DC Characteristics
Digital Inputs/Outputs

Parameter	Symbol	Min	Typ	Max	Units
Digital Inputs (CLKIN, SDIN, LOAD, RESET*, OPN)					
Input Low Voltage	VIL			0.8	V
Input High Voltage	VIH	2.0			V
Input Current	IIN	-200		200	nA
Digital Output (SDOUT)					
Output Low Voltage	VOL			0.4	V
Output High Voltage	VOH	2.4		VDD	V
Output Current Low	IOL			2.0	mA
Output Current High	IOH	-2.0			mA
Capacitive Load	CLOAD			15	pF

Driver Circuit

Parameter	Symbol	Min	Typ	Max	Units
Analog Inputs (DVH, DVL)					
High Level	DVH	DVL + 0.5		VAA + 0.1	V
Low Level	DVL	-0.25		DVH - 0.5	V
Input Current	IIN	-10		20	μA
Driver Output (VIO)					
Range	DRNG	-0.2		VAA	V
Driver Swing	DSWG	0.5		5.4	V
DC Output Current	IOUT	-50		50	mA
Output Impedance (Note 1)	ROUT	48		110	Ω
Output Impedance Accuracy (Note 2)	RACC		4		%
HiZ Leakage (DEN= 0) (Note 3)	IOZ	-1		1	μA
Open Circuit Leakage (Driver, comparator disconnected) at VIO (VEE to VXX)	IOC	-10		10	nA
DC Accuracy (Note 4)					
Offset Voltage (DVH – VIO, DVL – VIO)	VOS	-20		20	mV
Gain		0.99		1.01	V/V
Linearity		-0.1		0.1	% FSR
Digital Inputs to Driver					
Input Voltage Range	DHI(*), DEN(*)	0		VDD	V
Differential Input Swing	Input – Input*	±0.24		VDD	V
Input Current	IIN	-0.2		0.2	μA
External Reference Resistor	RREF	4.5		11	KΩ

DC conditions (unless otherwise specified): Over the full Recommended Operating Conditions”, including the full range of the power supplies.

Note 1: At $V_{IO} = (DVH + DVL) / 2$.

Note 2: Following calibration. Accuracy is measured as a percentage of $R_{REF}/100$.

Note 3: Comparator disconnected. Driver leakage specified for $0 \leq [V_{VIO} \text{ and } DVH \text{ and } DVL] \leq VAA$.

Note 4: Offset measured with input voltage (DVL or DVH) at the minimum value, and the gain error measured with the input voltage at the maximum allowed value. Measurements made with VIO unloaded.

TEST AND MEASUREMENT PRODUCTS

DC Characteristics (continued)

Comparator Circuit

Parameter	Symbol	Min	Typ	Max	Units
Analog Inputs (CVA, CVB) Voltage Range	V_{CVA}, V_{CVB}	-2.0		5.5	V
Input Current	IIN	-5		30	μ A
Input Differential Voltage Range [(VIO – CVA), (VIO – CVB)]	V_{DIFF}	-6.0		6.0	V
Hysteresis	VHYS		10		mV
Input Leakage (Driver disconnected) at VIO (–2.0 to +5.5V)	I_BIAS	-5		25	μ A
Input Leakage (Driver, Comparator disconnected) at VIO (VEE to VXX)	IOC	-10		10	nA
Offset Voltage	VOS	-20		20	mV
Digital Outputs (Figure 9) Differential Output Swing	VOD	250		450	mV
Common Mode Output Voltage Range	VCM	1.125		1.375	V
Change in VOD between Complimentary Output States	Δ VOD			\pm 45	mV

Continuity Test Circuit (CTC)

Parameter	Symbol	Min	Typ	Max	Units
CTCLV (Limit Voltage) Voltage Range		-2.0		0.0	V
Input Current	IIN	-1		10	μ A
Offset Error		-20		20	mV
Gain Error		-5		5	%
CTCFIV Input Current	IIN	-200		200	nA
CTC Output Compliance Voltage		CTCLV + 0.25		VAA - 1	V
CTC Output Current (Note 1) Programmable Range	ICTC	-250		-15	μ A
Offset		-15		15	μ A
Gain Error		-15		15	%

DC conditions (unless otherwise specified): Over the full Recommended Operating Conditions”, including the full range of the power supplies.

Note 1: Programmed by CTCFIV using the formula: $ICTC = 1.09 * [CTCFIV(V) / R_{E\text{REF}}(\Omega)]$. Offset and gain are calculated from calibration points at 10% and 90% of the 250 μ A full-scale range.

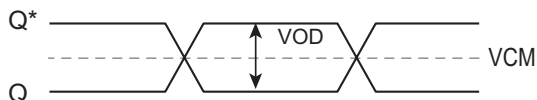


Figure 9. Comparator Outputs

TEST AND MEASUREMENT PRODUCTS

DC Characteristics (continued)

External PMU Switches, VIO/POUT Capacitance

Parameter	Symbol	Min	Typ	Max	Units
On-Resistance (EPMU Force Switch S4 to POUT) ($\pm 40\text{mA}$)			40	110	Ω
On-Resistance (EPMU Sense Switch S4 to POUT) ($\pm 4\text{mA}$)				500	Ω
On-Resistance (EPMUF and EPMUS Switch S7 to PMU_OUT) ($\pm 100\mu\text{A}$)		100		7000	Ω
On-Resistance (Driver Output to EPMUS Switch S3) ($\pm 100\mu\text{A}$)		100		7000	Ω
Leakage Current @ EPMUS (all channel's switches onto EPMU bus are open)		-10		10	nA
Leakage Current @ EPMUF (all channel's switches onto EPMU bus are open)		-15		15	nA
Capacitance @ EPMUS (all channels' switches onto EPMUS bus are open)			15		pF
Capacitance @ EPMUF (all channel's switches onto EPMU bus, open) (0 to 50 MHz)			35		pF
Capacitance at POUT (Switches Open) (Note 1)			12		pF
Capacitance @ VIO (S1 = Open, S2 = Closed)			15		pF
Capacitance @ VIO (S1 = S2 = Closed)			38		pF
Leakage Current at POUT (Switches Open) (Note 1)		-10		10	nA
Max Current for EPMU Force Paths		-40		40	mA
Max Current for EPMU Sense Paths		-4		4	mA
POUT Output Range with EPMUF $\leq +40\text{ mA}$		VEE		VXX - 2.5	V
POUT Output Range with EPMUF $\geq -40\text{ mA}$		VEE + 2.5		VXX	V
POUT Output Range with EPMUF $\pm 40\ \mu\text{A}$		VEE		VXX	V
PMU_OUT Leakage		-1		1	μA

DC conditions (unless otherwise specified): Over the full Recommended Operating Conditions”

Note 1: Includes the EPMU, Continuity Test and Pull-up Switches.

TEST AND MEASUREMENT PRODUCTS

DC Characteristics (continued)

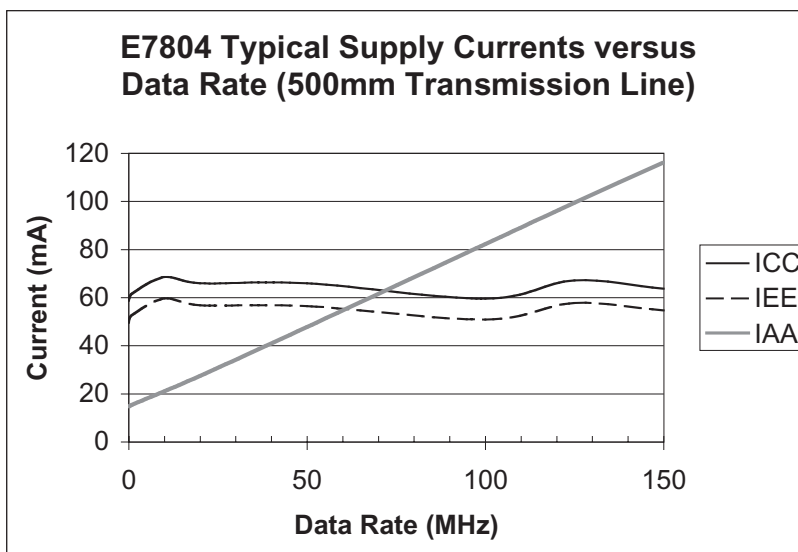
Pull-Up Resistor

Parameter	Symbol	Min	Typ	Max	Units
Pull-Up Resistor (including its switch)		1		3	KΩ
PUV Voltage Range		0		VAA	V
PUV Gain Error		-2		2	%
PUV Input Current		-3		3	μA
POUT Voltage Range with S6 Closed	V(POUT _{S6})	0		VAA	V

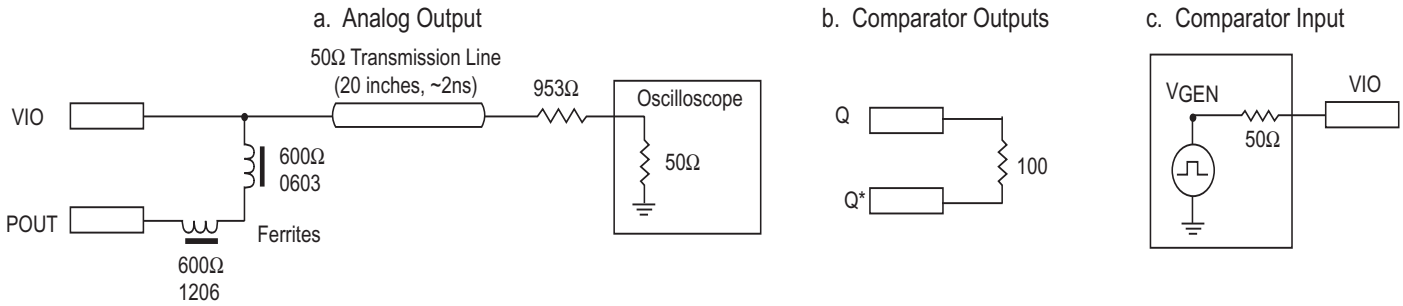
Power Supplies

Parameter	Symbol	Min	Typ	Max	Units
Max Quiescent Power Supply Consumption (Note 1)					
Positive Analog Supply 1	ICC		60	90	mA
Positive Analog Supply 2	IAA		18	30	mA
Digital Supply	IDD		55	80	mA
Negative Power Supply	IEE	-80	-45		mA
Switch Power Supply	IXX		1	4	mA

Note 1: CLKIN Low, no VIO output currents, comparators with 100Ω floating terminations.



The above graph depicts supply current variation with respect to all the Drivers concurrently driving the same 3V output swings over frequency into a 50Ω unterminated transmission line while also connected to the window comparators.



NOTE: Driver propagation delays specified with transmission line delay removed.

Figure 10. AC Test Circuits

TEST AND MEASUREMENT PRODUCTS
AC Characteristics (continued)
Comparator Circuit (Driver S1 Open)

Parameter	Symbol	Min	Typ	Max	Units
Propagation Delay (0 to 3V Input) (Figure 16)					
Note 4	Tpd(+),(-)	3.5		7.5	ns
Note 5	Tpd(+),(-)	3.0		6.0	ns
Digital Output Rise and Fall Times (20% - 80%) (into 100Ω floating termination)	Tr, Tf		550		ps
Minimum Pulse Width (Note 1)				6	ns
Propagation Delay Matching (Note 5)	Tpd(+),(-)			1.0	ns

Driver Circuit

Parameter	Symbol	Min	Typ	Max	Units
Propagation Delay (0 to 3V Output) (Note 2, Figure 17)					
Data (DHI) to Output					
Note 4	TPLH, TPHL	3.5		6.5	ns
Note 5	TPLH, TPHL	3.4		5.7	ns
Enable to HiZ (Figure 12)	TPAZ	3.0		6.5	ns
Enable to Output Active (Figure 12)	TPZA	3.0		6.5	ns
Propagation Delay Match (Tpd(+) to Tpd(-)) (Note 5)	Tpd(+) to (-)			1.0	ns
Rise/Fall Times					
0 to 800 mV (20% - 80%)	Tr/Tf			2.0	ns
0 to 3V (10% - 90%)	Tr/Tf	2.4		2.5	ns
0 to 5V (10% - 90%)	Tr/Tf			3.0	ns
Fmax (Note 3, Figure 13)					
800 mV	Fmax	133			MHz
3V	Fmax	133			MHz
5V	Fmax	100			MHz
Minimum Pulse Width (Note 3, Figure 14)					
0 to 800 mV	Tpw+, Tpw-			3.0	ns
0 to 3V	Tpw+, Tpw-			3.0	ns
0 to 5V	Tpw+, Tpw-			4.5	ns

AC Test Conditions (unless otherwise specified): "Recommended Operating Conditions."

Note 1: For 3V input while maintaining less than 300ps of propagation delay variation.

Note 2: Driver propagation delays are measured with LVDS differential logic inputs at DHI and DEN. Output delay is specified with transmission line delay removed.

Note 3: At less than 10% output amplitude attenuation, DVL = 0V.

Note 4: Over all recommended operating conditions and junction temperatures.

Note 5: VDD at 3.3V, VCC = 8.2V, VEE = -5V, junction temperature at 45°C.

TEST AND MEASUREMENT PRODUCTS
AC Characteristics (continued)
Driver Performance

Parameter	Symbol	Min	Typ	Max	Units
Driver Temp. Coefficient ($\Delta t_{pd}/\Delta T$) (Note 4)	$\Delta t_{pd}/^{\circ}C$			10	ps/ $^{\circ}C$
Driver Tpd Dispersion vs. Amplitude (Note 1, Figure 11)	Δt_{pd} (Swing)		0.7	1	ns
Driver Tpd Dispersion vs. Common Mode (Note 2, Figure 11)	Δt_{pd} (cm)		0.8	1	ns
Driver Tpd Dispersion vs. Pulse Width (Note 3, Figure 15)	Δt_{pw}		0.3	0.4	ns

Comparator Performance

Parameter	Symbol	Min	Typ	Max	Units
Comparator Temp. Coefficient ($\Delta t_{pd}/\Delta T$)	$\Delta t_{pd}/^{\circ}C$		6	10	ps/ $^{\circ}C$
Comparator Tpd Dispersion vs. Overdrive (Figure 17)			1.5	2	ns
Comparator Tpd Dispersion vs. Common Mode (Figure 18)			1.1	1.5	ns
Comparator Tpd Dispersion vs. Edge Rate (Figure 19)			0.8	1.0	ns
Comparator Waveform Tracking Dispersion (Figure 20)			3.0	3.5	ns
Comparator Tpd Dispersion vs. Pulse Width (Figure 21)			0.4	0.7	ns

Internal Switches

Parameter	Symbol	Min	Typ	Max	Units
OPN Input to S1 and S2, Time to:					
Disconnect				1	μs
Connect				1	μs
PMU to POUT, S4, Connect/Disconnect (measured from valid LOAD and CLKIN edges) (Note 5)				1	μs

Note 1: Variation in propagation delay when DVL = 0, vary DVH from 0.5V to 5.0V.

Note 2: Driver Output = 0.8V swing. Common mode = 1.0V to 3.0V.

Note 3: Propagation delay change when going from long to short pulse widths.

Note 4: DVL = 0V, DVH = 3V.

Note 5: Switches S1-S6 open on the fourth (4th) low-going CLKIN edge after a LOAD signal is applied.

S1-S6 will close on the fifth (5th) low-going CLKIN edge.

Switch S7 will open or close on the fourth (4th) low-going CLKIN edge after LOAD.

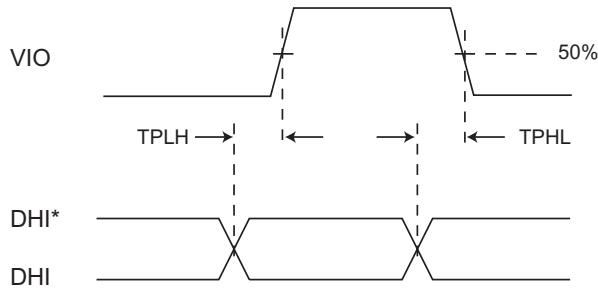
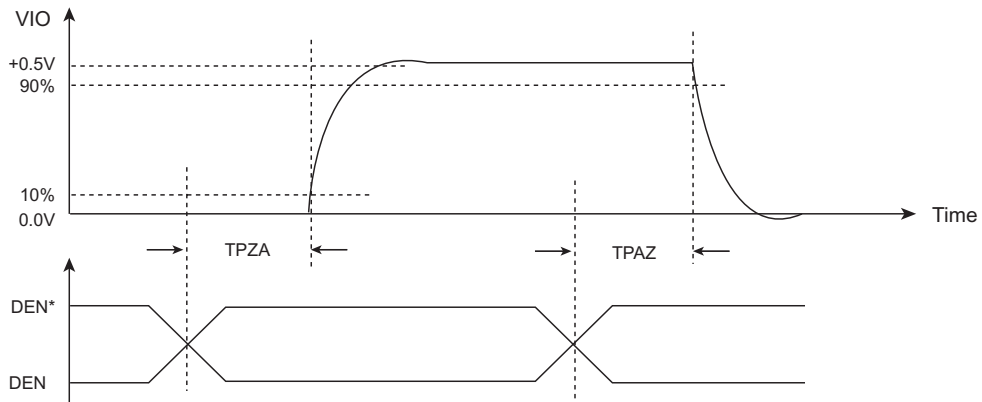


Figure 11. Driver Propagation Delay Measurements



Transmission line terminated 50Ω to ground.

Figure 12. Driver HiZ Enable/Disable Delay Measurement Definition

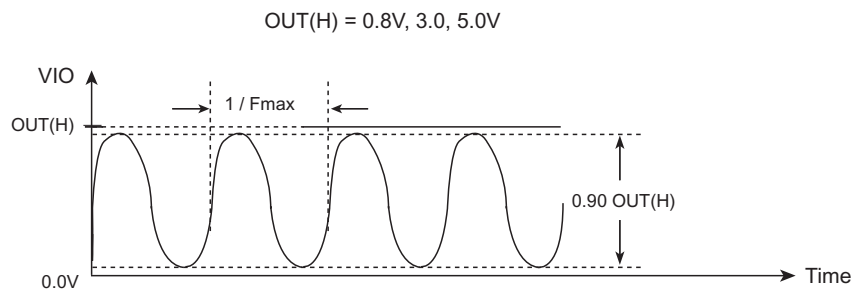


Figure 13. Driver Fmax Measurement Definition

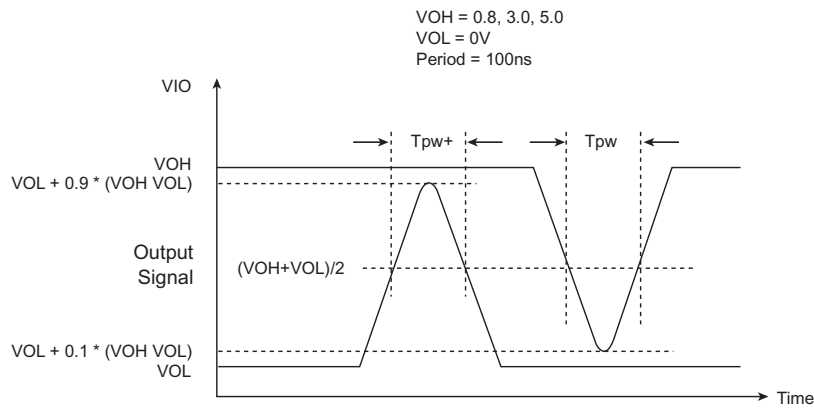


Figure 14. Driver Minimum Pulse Width Measurement Definition

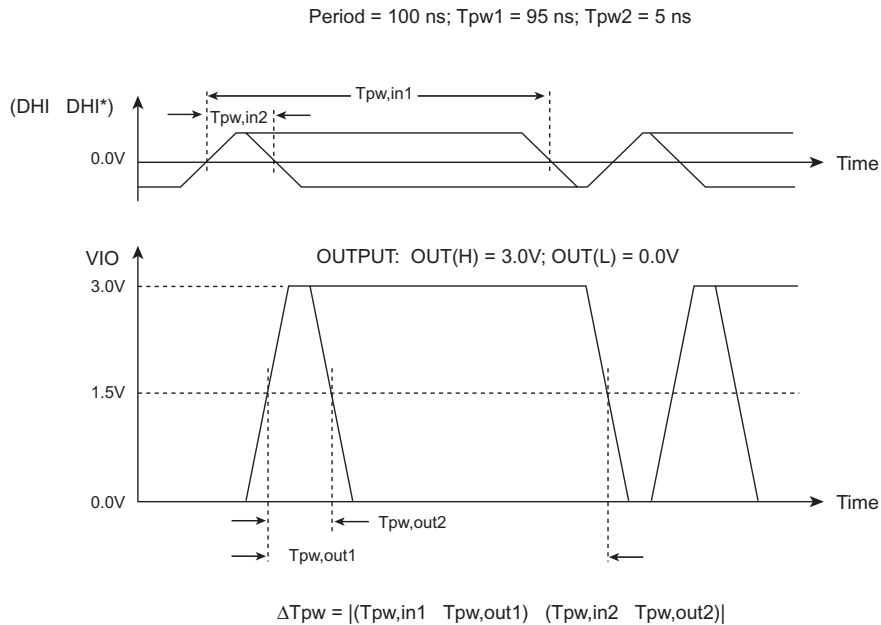


Figure 15. Driver Dispersion: Pulse Width Measurement Definition

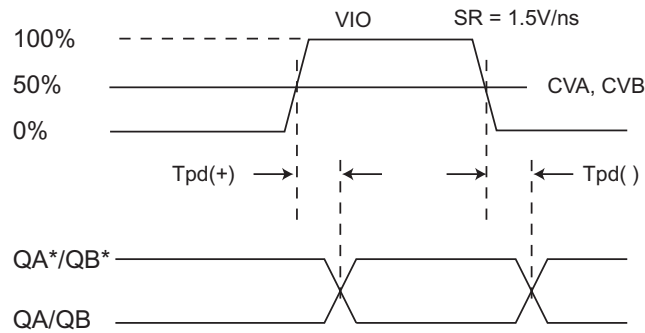


Figure 16. Comparator Propagation Delay Measurements

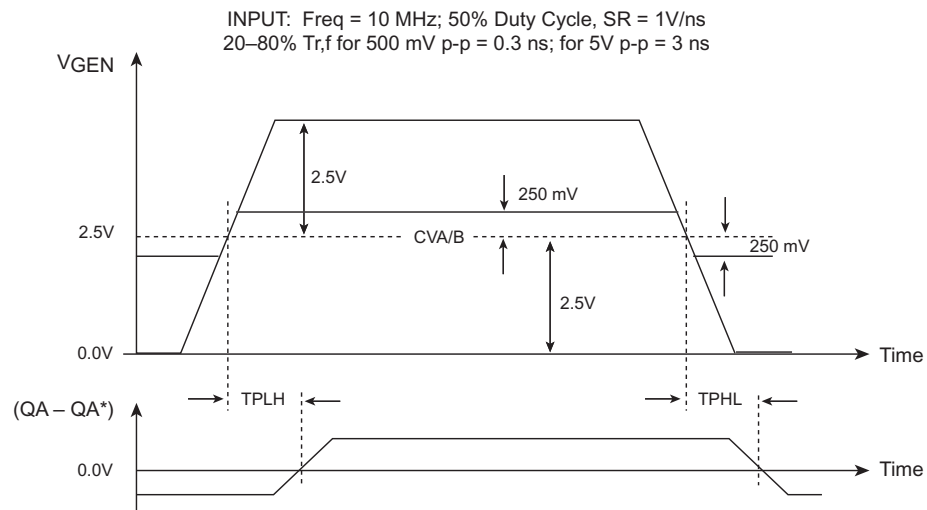


Figure 17. Comparator Dispersion: Overdrive Measurement Definition

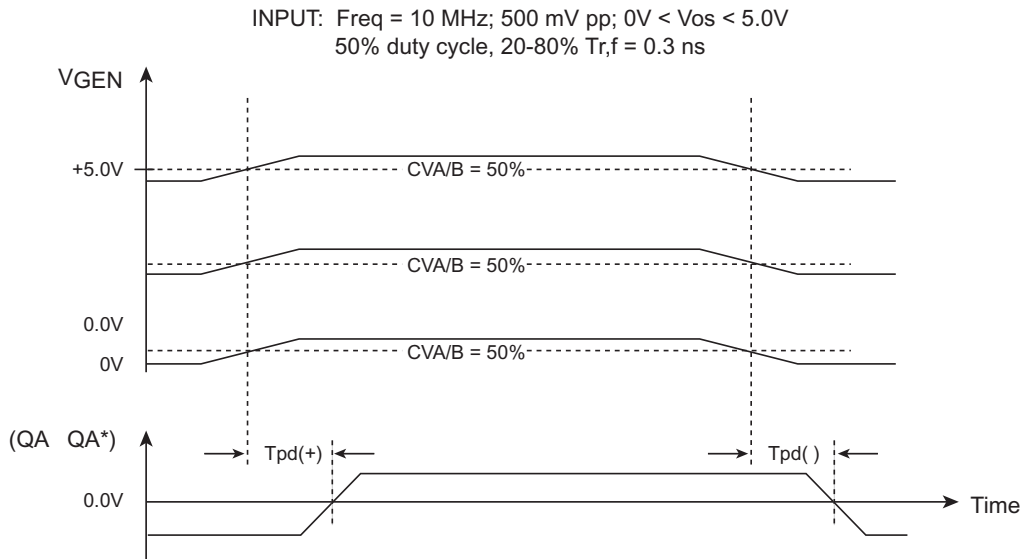
TEST AND MEASUREMENT PRODUCTS
AC Characteristics (continued)


Figure 18. Comparator Dispersion: Common Mode Measurement Definition

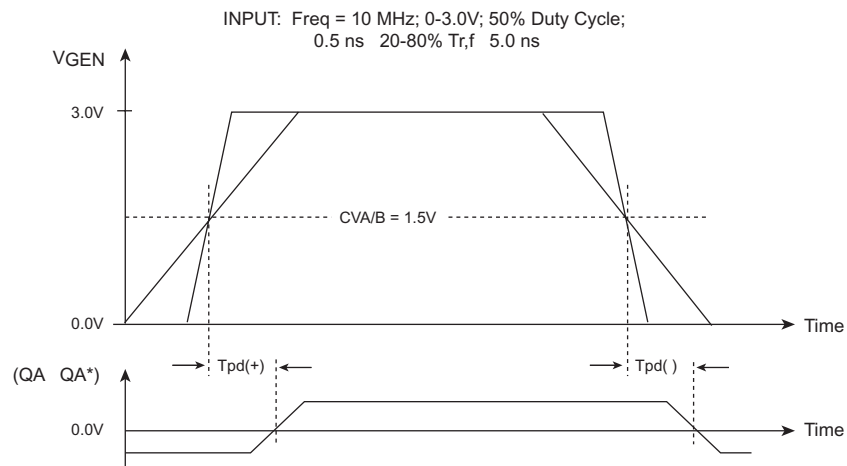


Figure 19. Comparator Input Slew Rate Measurement Definition

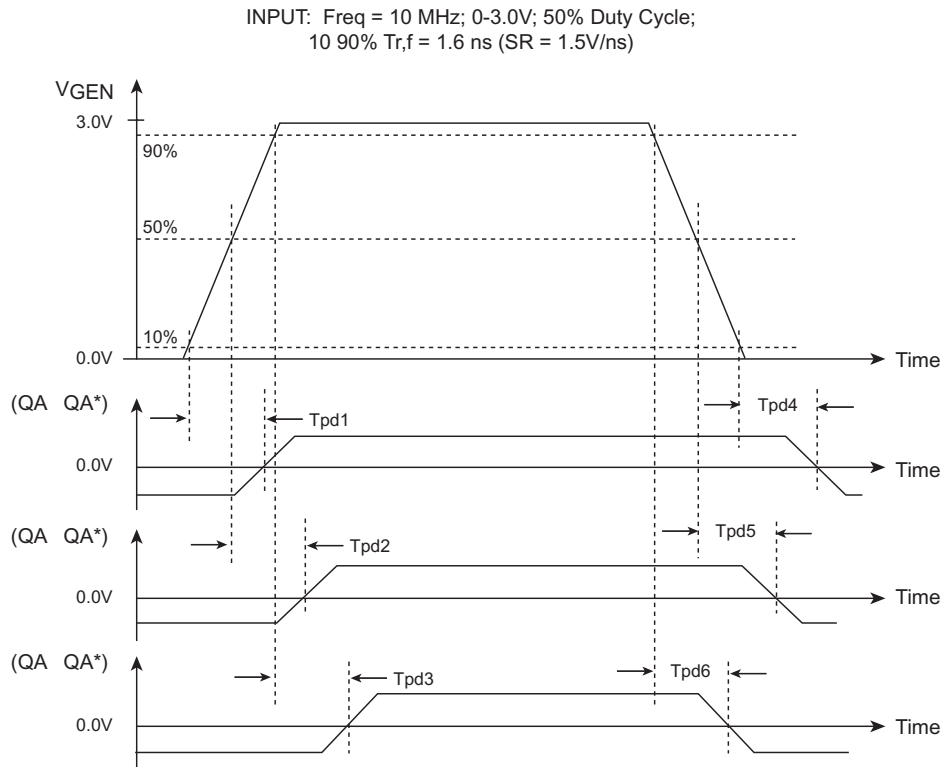


Figure 20. Comparator Dispersion: Waveform Tracking Measurement Definition

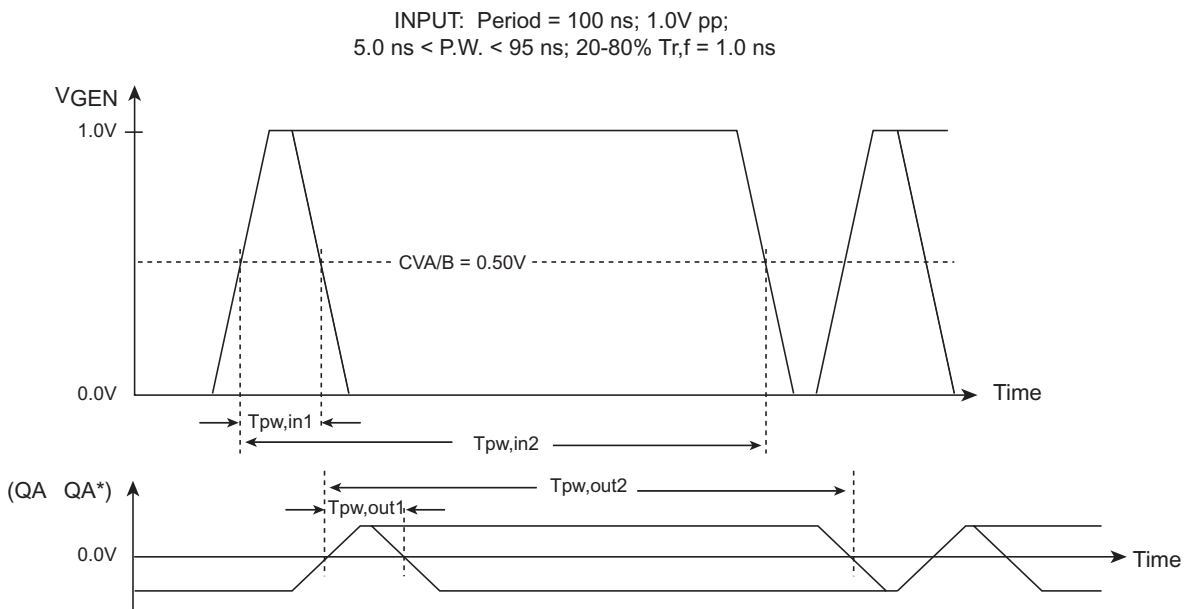


Figure 21. Comparator Dispersion: Pulse Width Measurement Definition

TEST AND MEASUREMENT PRODUCTS
AC Characteristics (continued)
Logic Specifications (Figure 22)

Parameter	Symbol	Min	Typ	Max	Units
Set up Times (to CLKIN rising edge)					
SDIN	T_{SU_SDIN}	3			ns
LOAD	T_{SU_LD}	5.0			ns
Hold Times (to CLKIN rising edge)					
SDIN	T_{HLD_SDIN}	5.0			ns
LOAD	T_{HLD_LD}	8.0			ns
Output Delay Times (to CLKIN falling edge)					
SDOUT	T_{SDOUT}	0.5		7.0	ns
CLKIN					
Fmax	Fmax			33.0	MHz
Clock High Time	T_{CLKH}	10			ns
Clock Low Time	T_{CLKL}	10			ns
RESET to Clock Hold-Off Time (Note 1)	T_{RST_IN}	10			ns
RESET Pulse Width	PW_{RESET}	20			ns

Note 1: After an external RESET* event, valid input signals (SDIN and CLKIN) should be held off to allow internal gates to exit RESET. SDIN and CLKIN edges may be present before T_{RST_IN} , but the clocked states cannot be guaranteed. The RESET signal is asynchronous on both assertion and de-assertion.

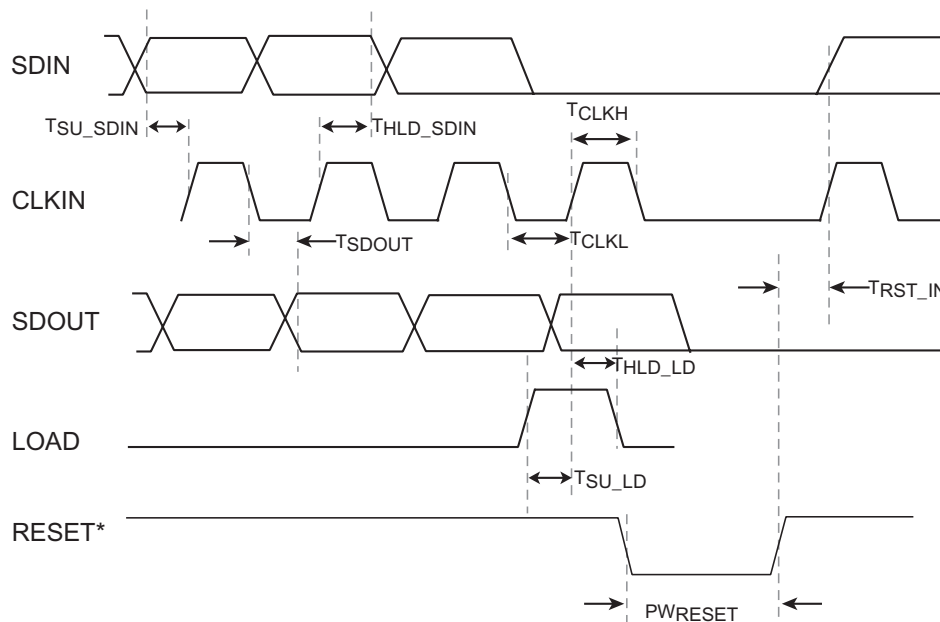


Figure 22. Logic Timing Diagram

TEST AND MEASUREMENT PRODUCTS**Ordering Information**

Model Number	Package
E7804BHFT	128-Pin, 14x20x2mm MQFP 0.5mm Lead Pitch (with Internal Heat Spreader)
EVM7804BHFT	E7804 Evaluation Board



This product is lead-free.

Contact Information

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